

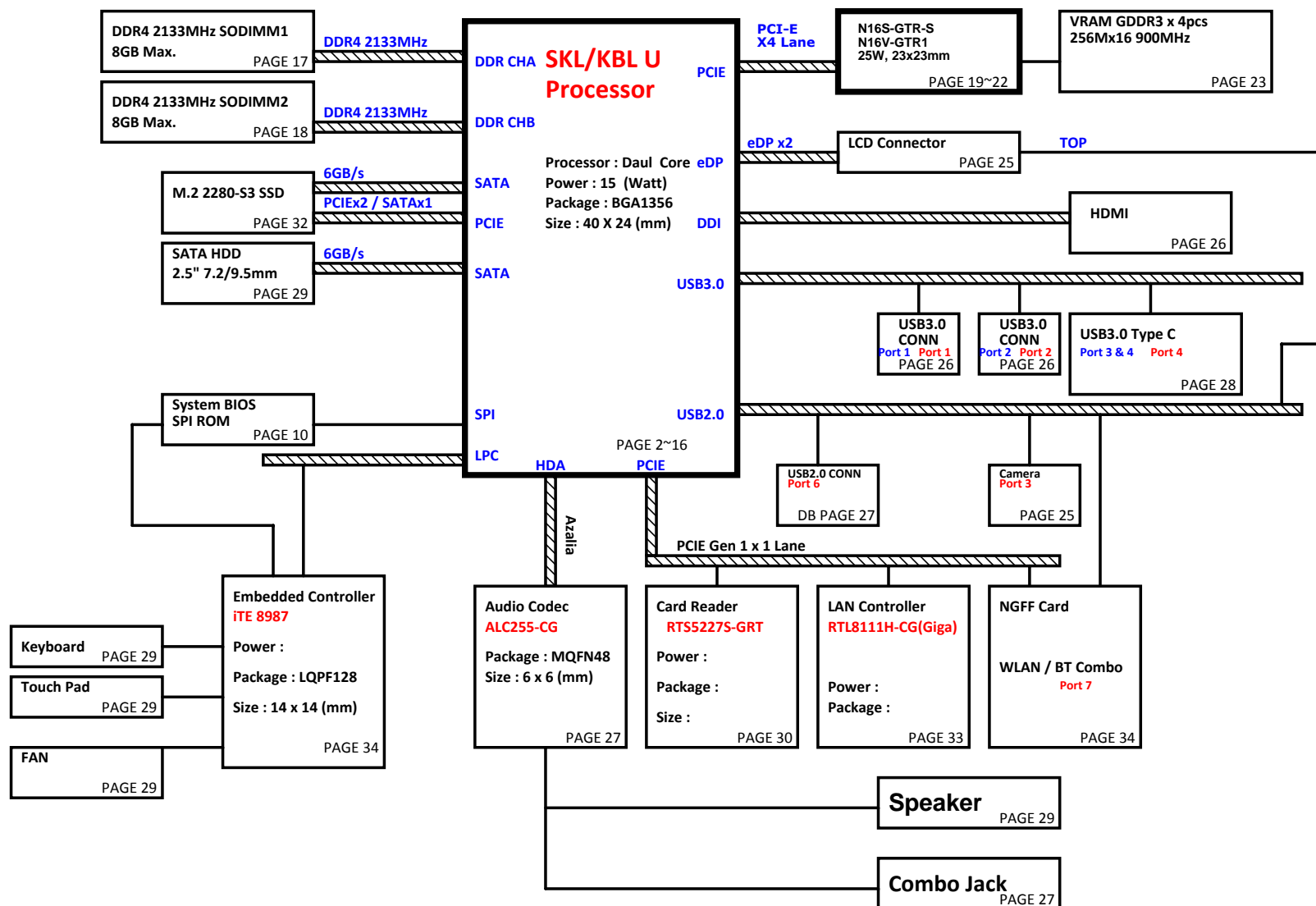
DIS (15")

LG9

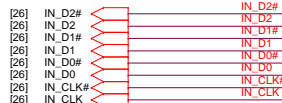
Intel SKL/KBL ULT Platform Block Diagram

PCB 6L STACK UP

LAYER 1 : TOP
 LAYER 2 : SGND
 LAYER 3 : IN1(High)
 LAYER 4 : IN2(Low)
 LAYER 5 : SVCC
 LAYER 6 : BOT


www.schematic-x.blogspot.com

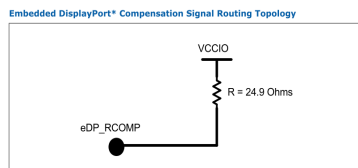
2 K Ω \pm 5% pull-up
up to 5V after the



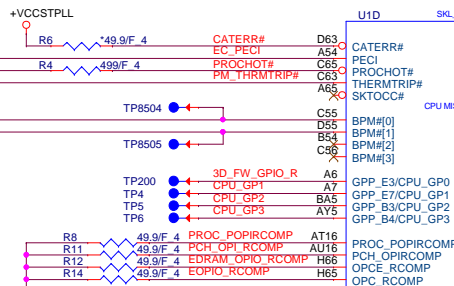
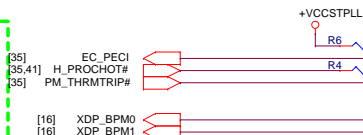
0317 CQ
Del R868 & R869 2.2K PU +3V (重複)



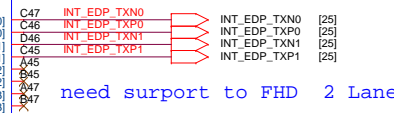
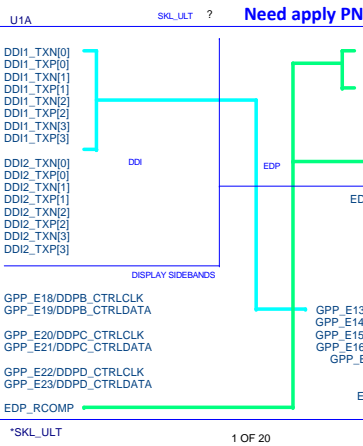
eDP_COMPIO and ICOMPO signals should be shorted near balls and routed with typical impedance <25 ohms



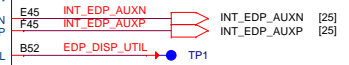
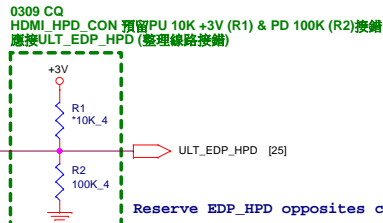
Processor pull-up (CPU)
TO BE REPLACED WITH 1K OHMS FOR SKL .
470 OHM IS FOR I/P



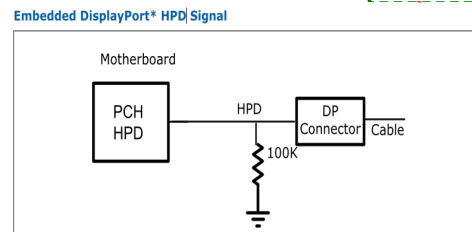
Rcomp < 600mil



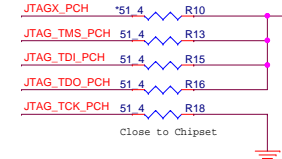
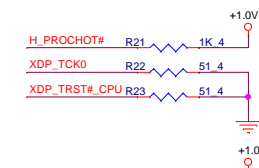
need surport to FHD 2 Lane

0224 CQ
Del INT_HDMI_AUXN & INT_HDMI_AUXN
HDMI 1.4 規格対応

Reserve EDP HPD opposites circuit!



PLACE NEAR CPU



[17]	M_A_DQSN[7:0]	
[17]	M_A_DQSP[7:0]	
[18]	M_B_DQSN[7:0]	
[18]	M_B_DQSP[7:0]	
[17]	M_A_DQ[63:0]	
[18]	M_B_DQ[63:0]	

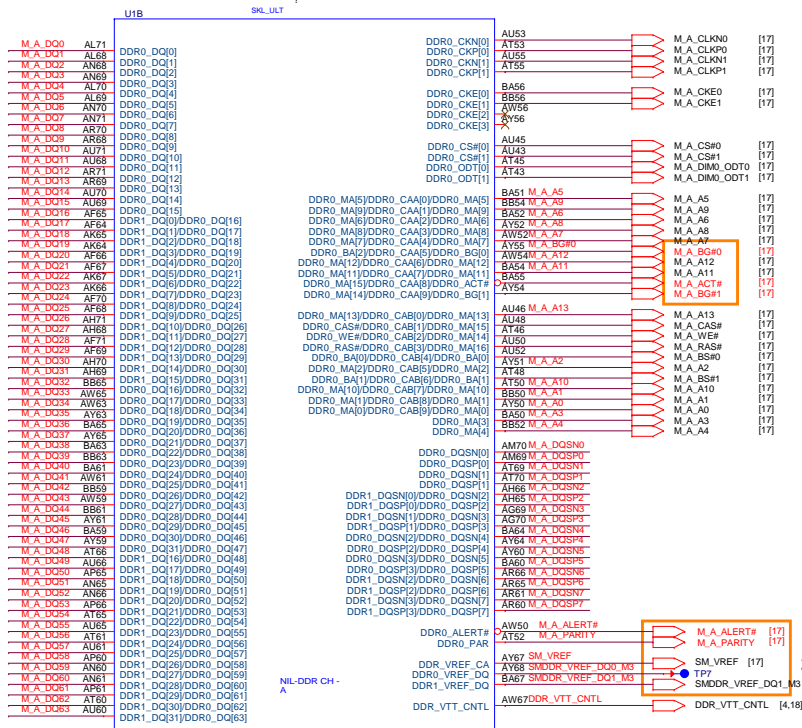
[6,17,18,38,40,48] +1.2VSUS

SkyLake ULT Processor (DDR4)

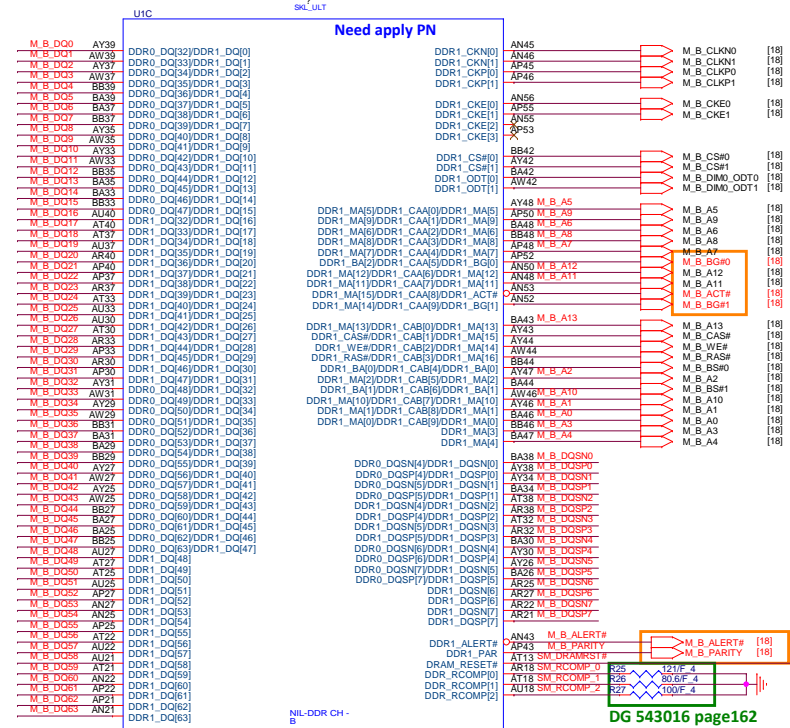
Non-Interleave / side by side

Need apply PN

Need apply PN



*SKL_ULT 2 OF 20
REV = 1



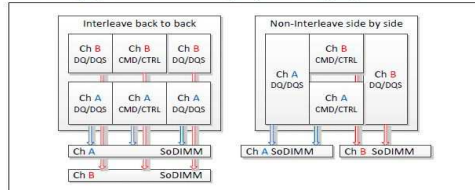
*SKL_ULT 3 OF 20
REV = 1

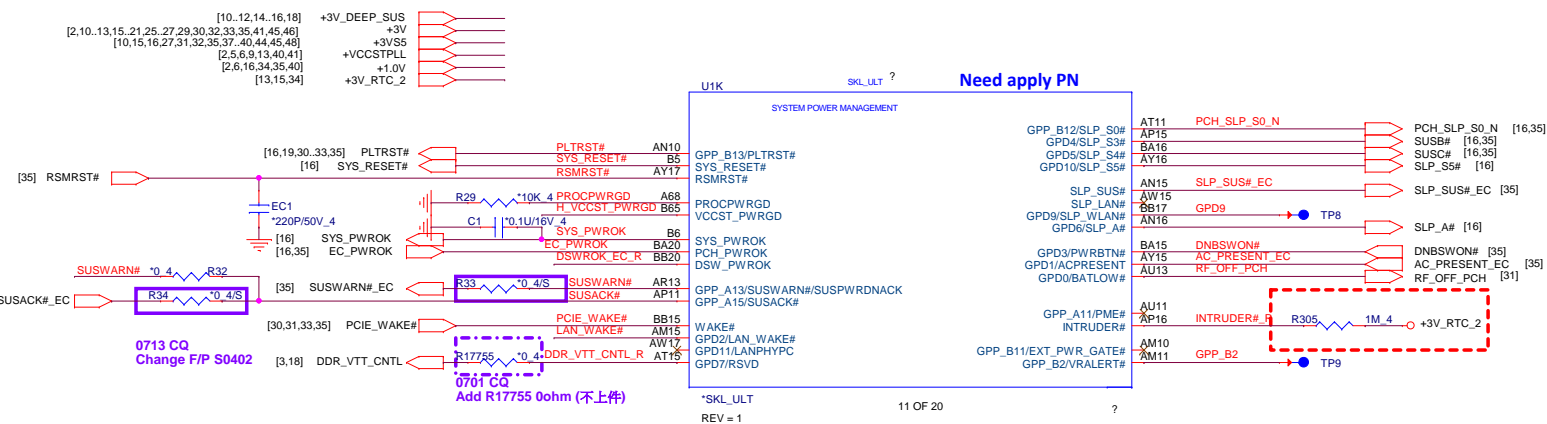
+1.2VSUS

R24

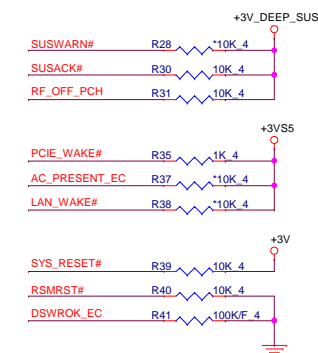
DDR4_DRAMRST# [17,18]

Interleave (IL) and Non-Interleave (NIL) Modes Mapping



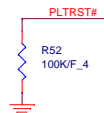


PCH Pull-high/low(CLG)

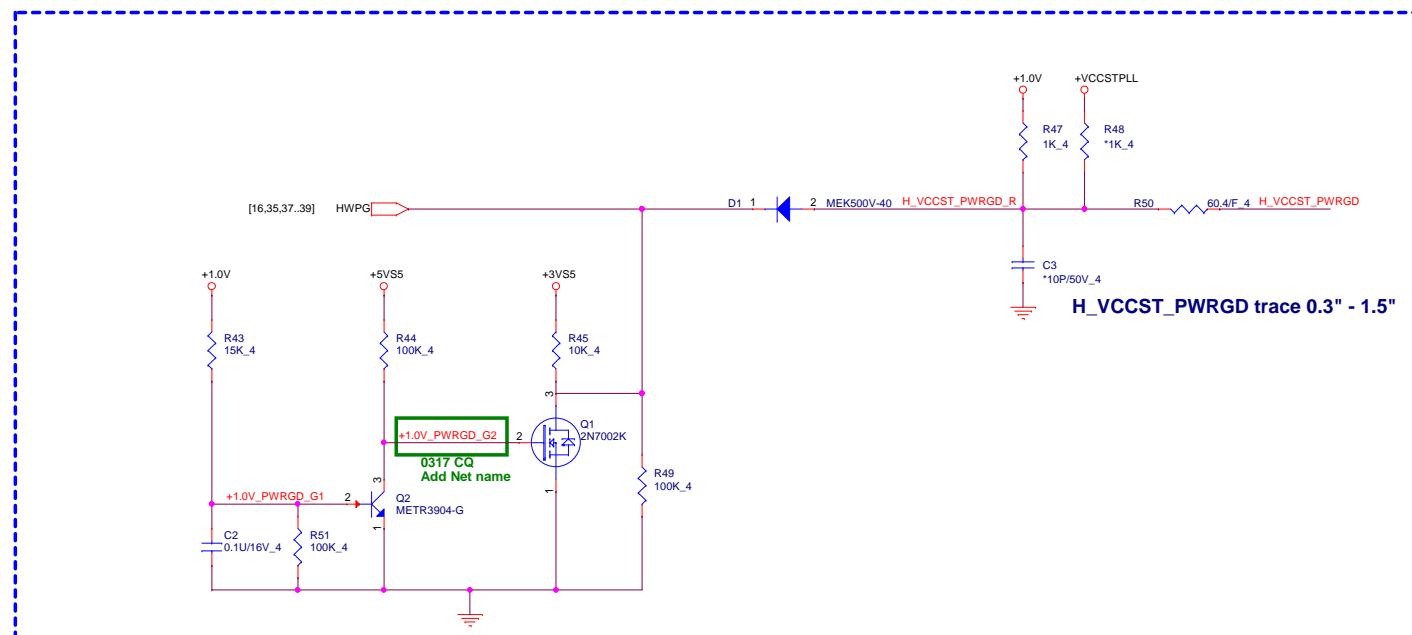
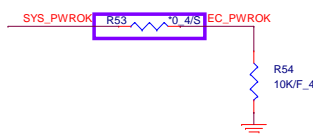


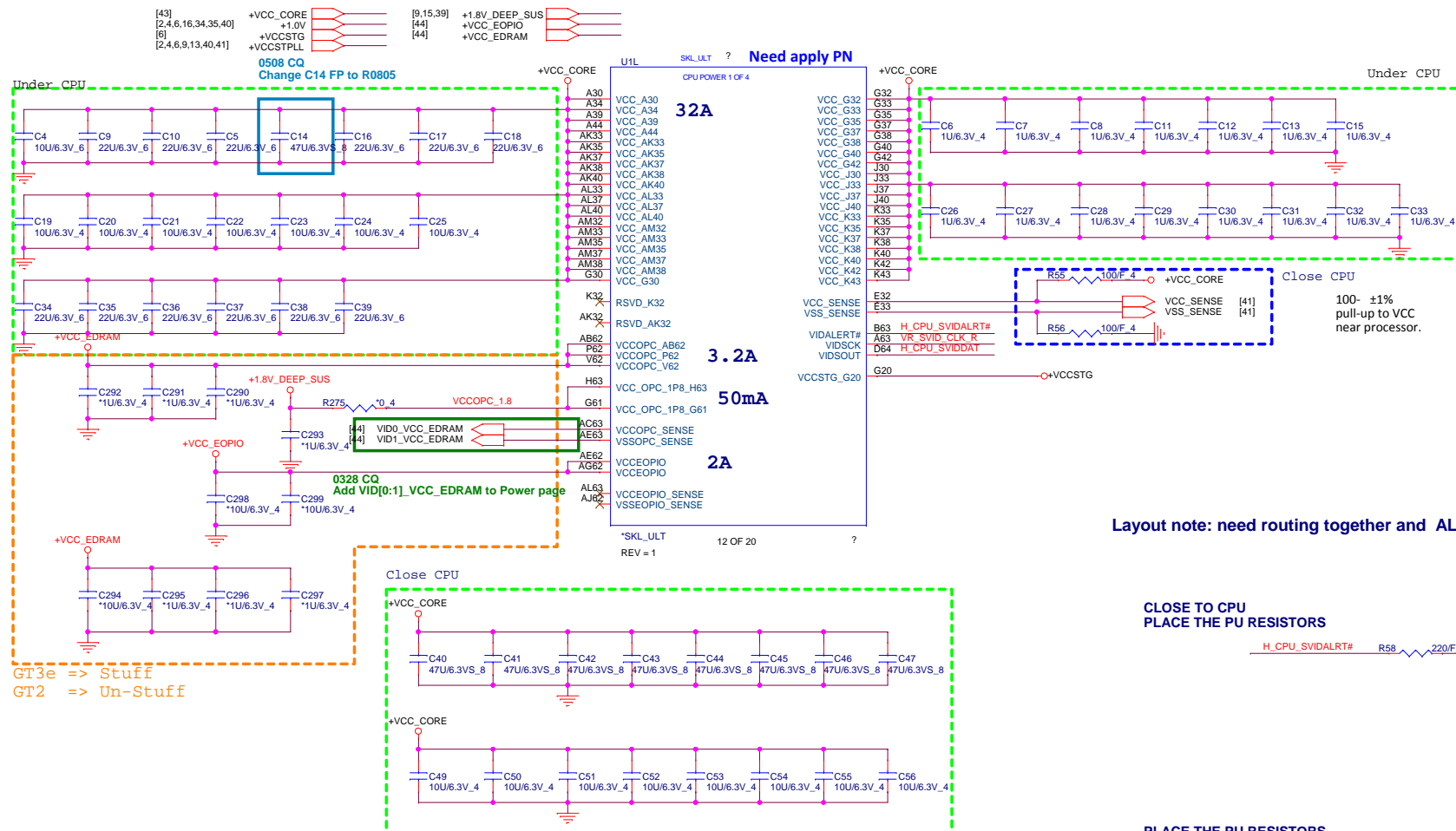
PLTRST#(CLG)

Rise/Fall time less than 100ns

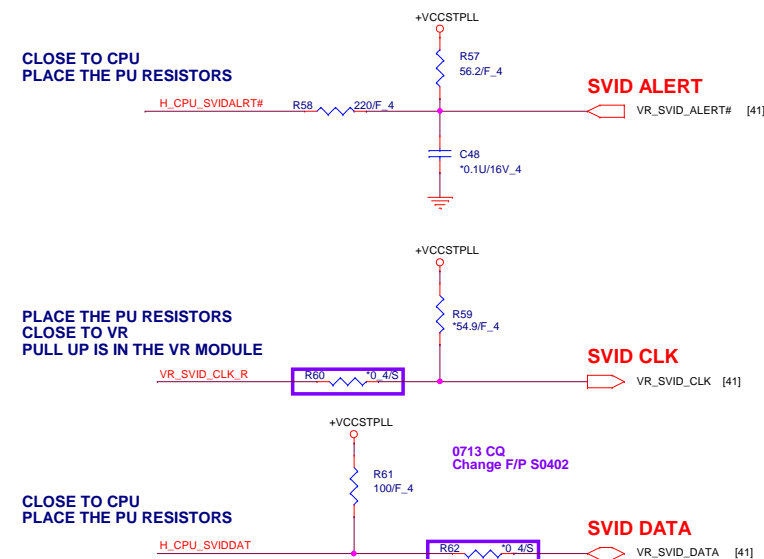


System PWR_OK(CLG)

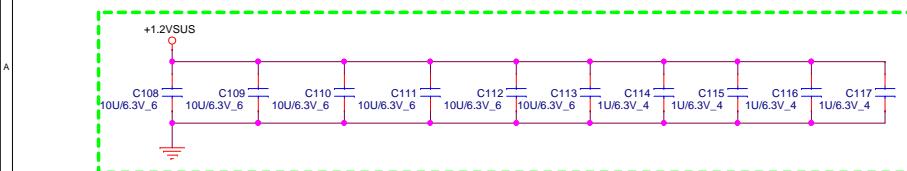
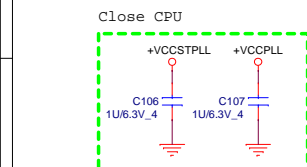
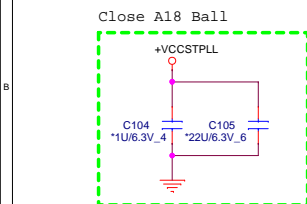
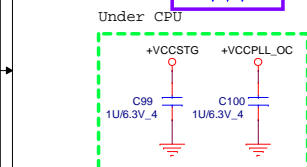
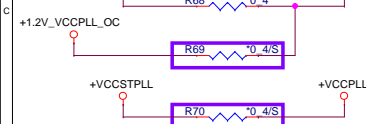




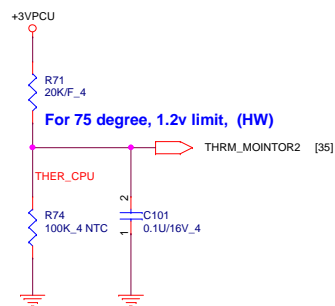
Layout note: need routing together and ALERT need between CLK and DATA.



Power Rail	Description	Control
V _{CC}	Processor IA Cores Power Rail	SVID
V _{CCGT}	Processor Graphics Power Rails	SVID
V _{CCGTX}	Processor Graphics Extended Power Rail Available only for GT3/GT4 processor SKUs	SVID
V _{CCSA}	System Agent Power Rail	SVID/Fixed (SKU dependent)
V _{CCIO}	IO Power Rail	Fixed
V _{CCST}	Sustain Power Rail	Fixed
V _{CCPLL}	Processor PLLs power rail	Fixed
V _{DDQ}	Integrated Memory Controller Power Rail	Fixed (Memory technology dependent)
V _{CCOPC}	Processor OPC power rail (available only in SKU's with OPC)	Fixed
V _{CCOPC_1P8}	Processor OPC power rail (available only in SKU's with OPC)	Fixed
V _{CCEOPIO}	Processor EOPIO power rail (available only in SKU's with OPC)	Fixed



For CPU USE

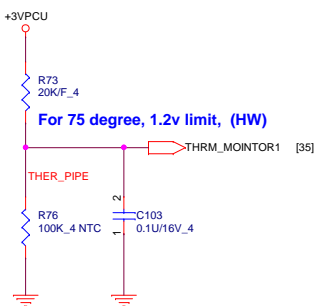


For 75 degree, 1.2v limit, (HW)

THER_CPU

IO Thrm Protect

For PIPE USE



For 75 degree, 1.2v limit, (HW)

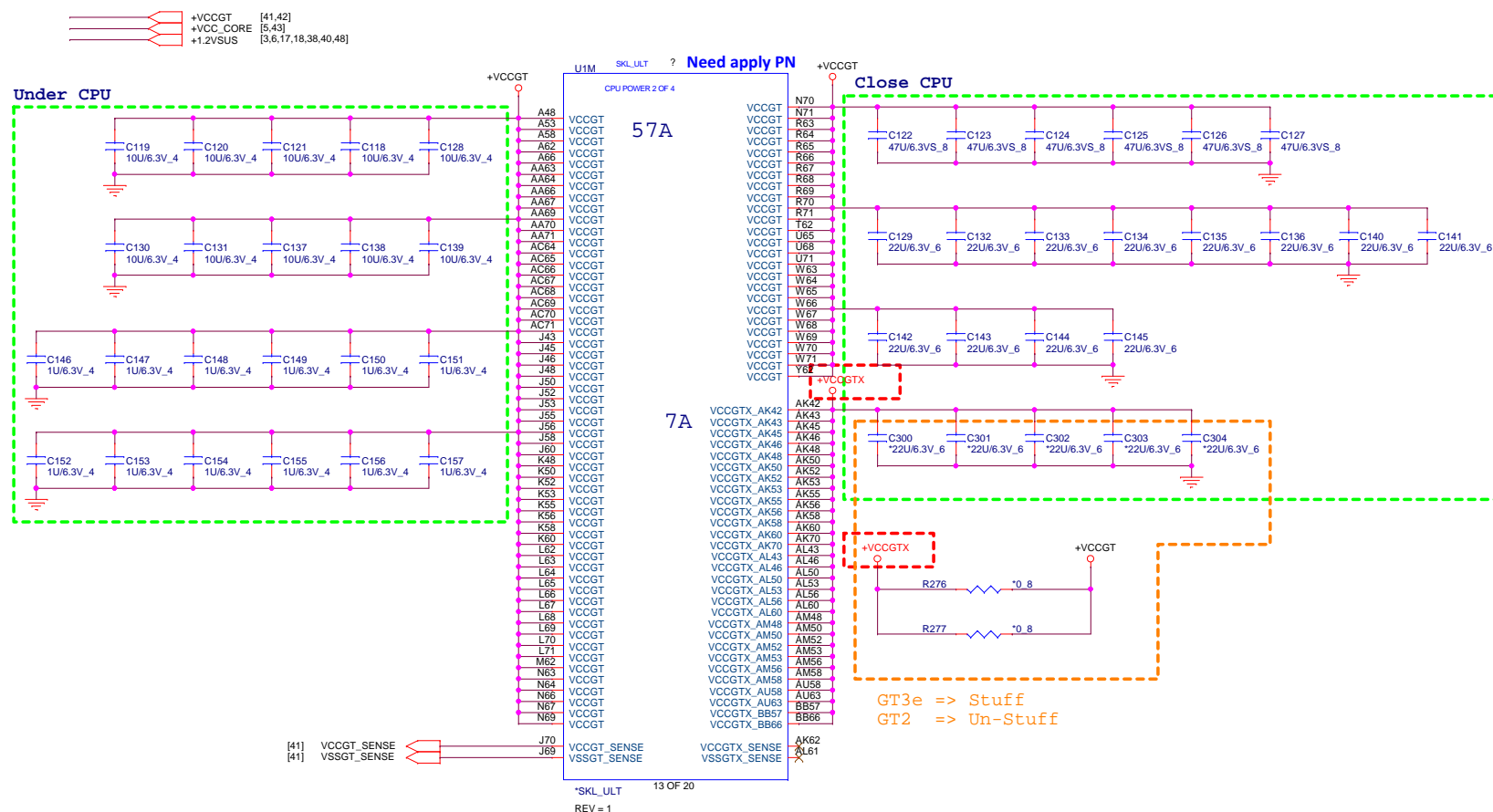
THER_PIPE

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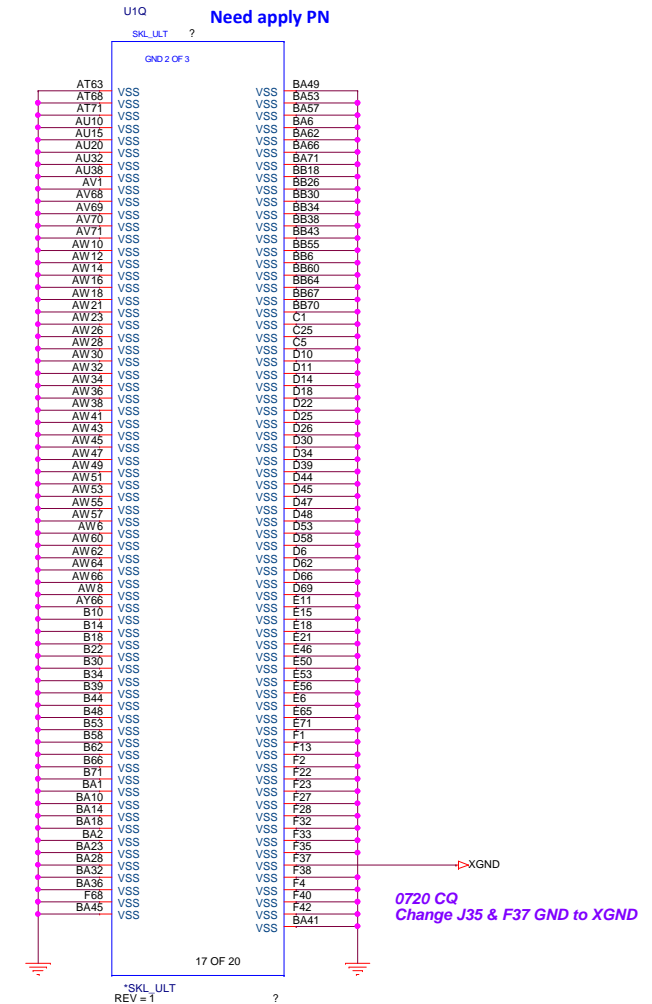
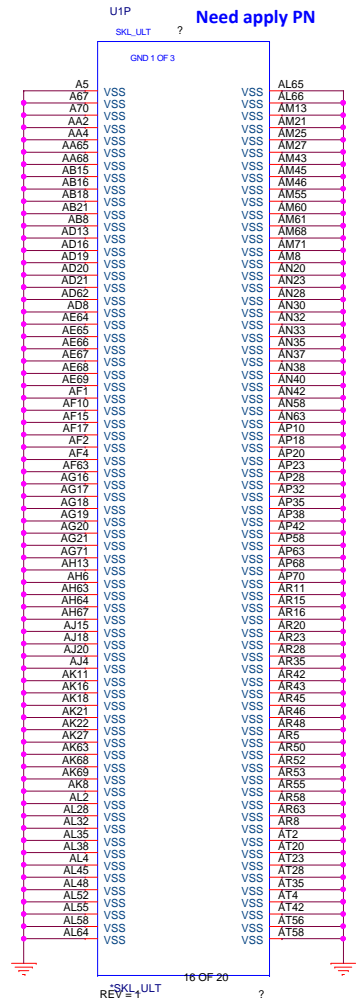
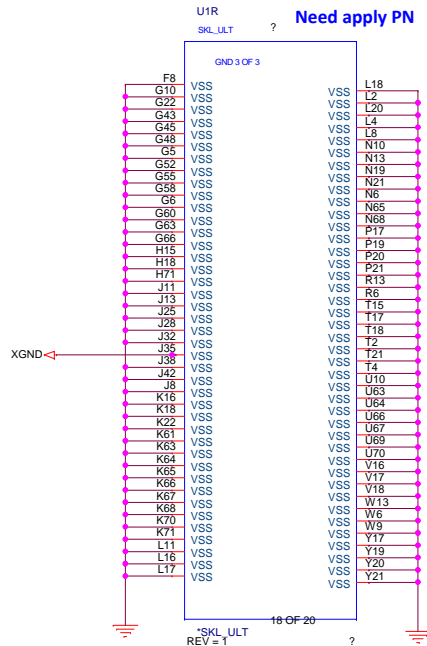


PROJECT : LG9
Quanta Computer Inc.

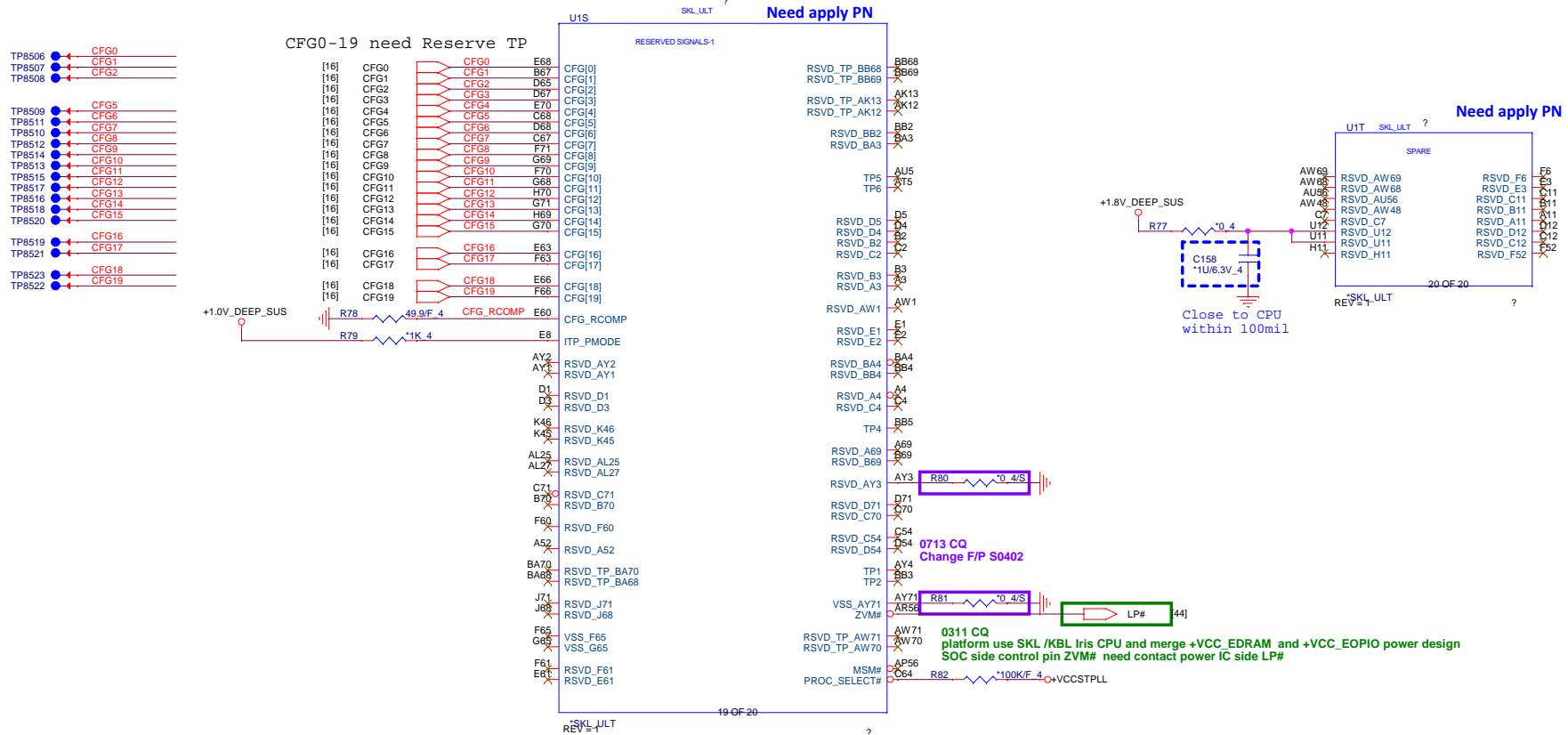
Size Custom	Document Number SKL-05 [POWER-2]	Rev 1A
Date: Wednesday, July 20, 2016		Sheet 6 of 49



Power Rail	Description	Control
V _{CC}	Processor IA Cores Power Rail	SVID
V _{CCGT}	Processor Graphics Power Rails	SVID
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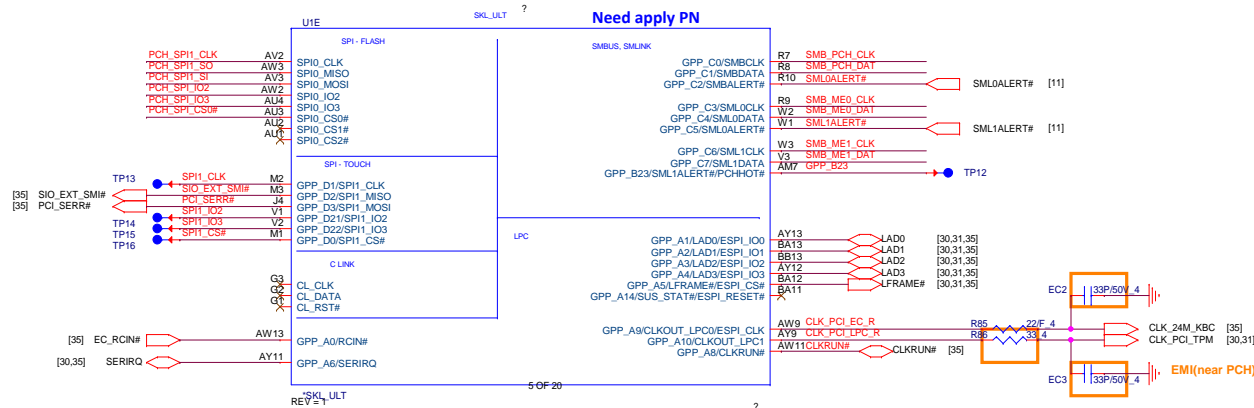
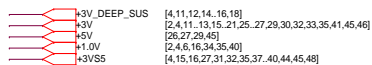


[5,15,39] +1.8V_DEEP_SUS
[15,16,39,40] +1.0V_DEEP_SUS

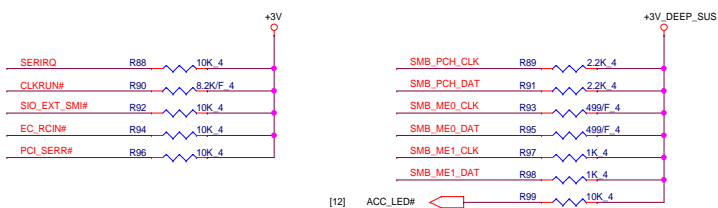


Processor Strapping The CFG signals have a default value of '1' if not terminated on the board.

	1	0	Circuit
CFG3 (Physical Debug Enable) DFX_Privacy	Disable:	Enable: Set DFX Enable in DFX interface MSR	CFG3 R83 ~1K 4
CFG4 (DP Presence Strap)	Disable; No physical DP attached to eDP	Enable; An ext DP device is connected to eDP	CFG4 R84 ~1K 4



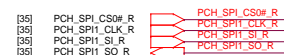
GPIO Pull UP



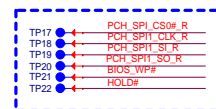
PCH SPI ROM(CLG)

3/31 CQ
Fix ROM PN

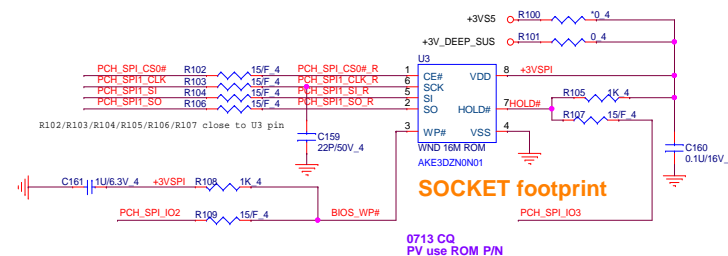
Vender	Size	P/N
Winbond	16MB	AKE3DZN0N01 - IC FLASH(8P) W25Q128FVSIQ(SOIC)
GGD	16MB	AKE3DF0Q000 - IC FLASH(8P)GD25B128CSIQR(SOP)
Socket		DFHS08FS023



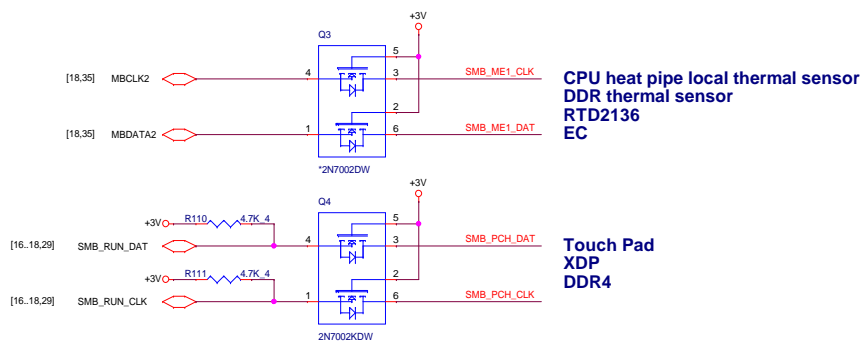
need place to TOP



PCH SPI ROM(CLG)

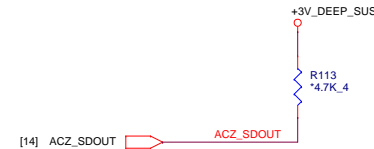
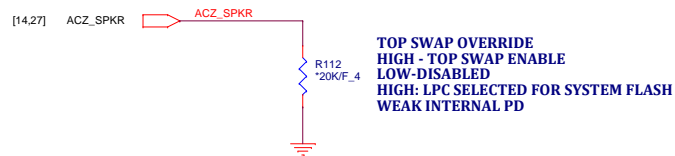


SMBus/Pull-up(CLG)

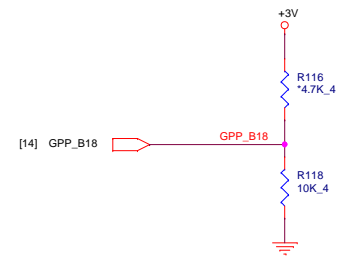
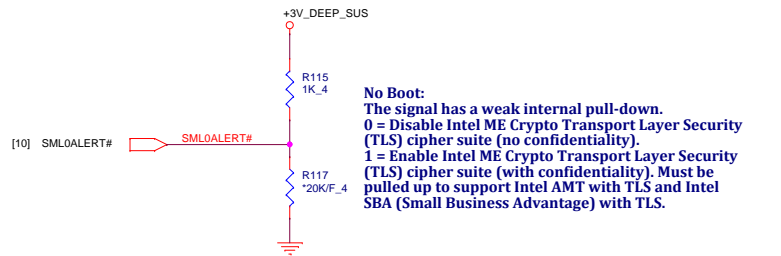


Functional Strap Definitions

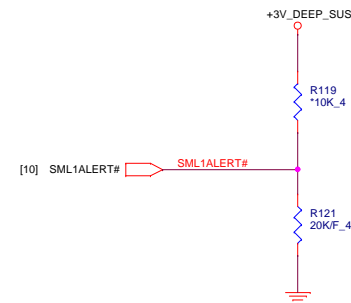
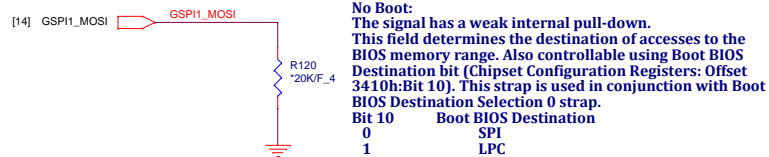
DESIGN NOTE:
WEAK PULL UP RESISTOR PRESENT ON THIS NET



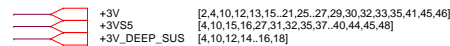
No Boot:
The signal has a weak internal pull-down.
0 = Enable security measures defined in the Flash Descriptor.
1 = Disable Flash Descriptor Security (override). This strap should only be asserted high using external pull-up in manufacturing/debug environments ONLY. This function is useful when running ITP/XDP.

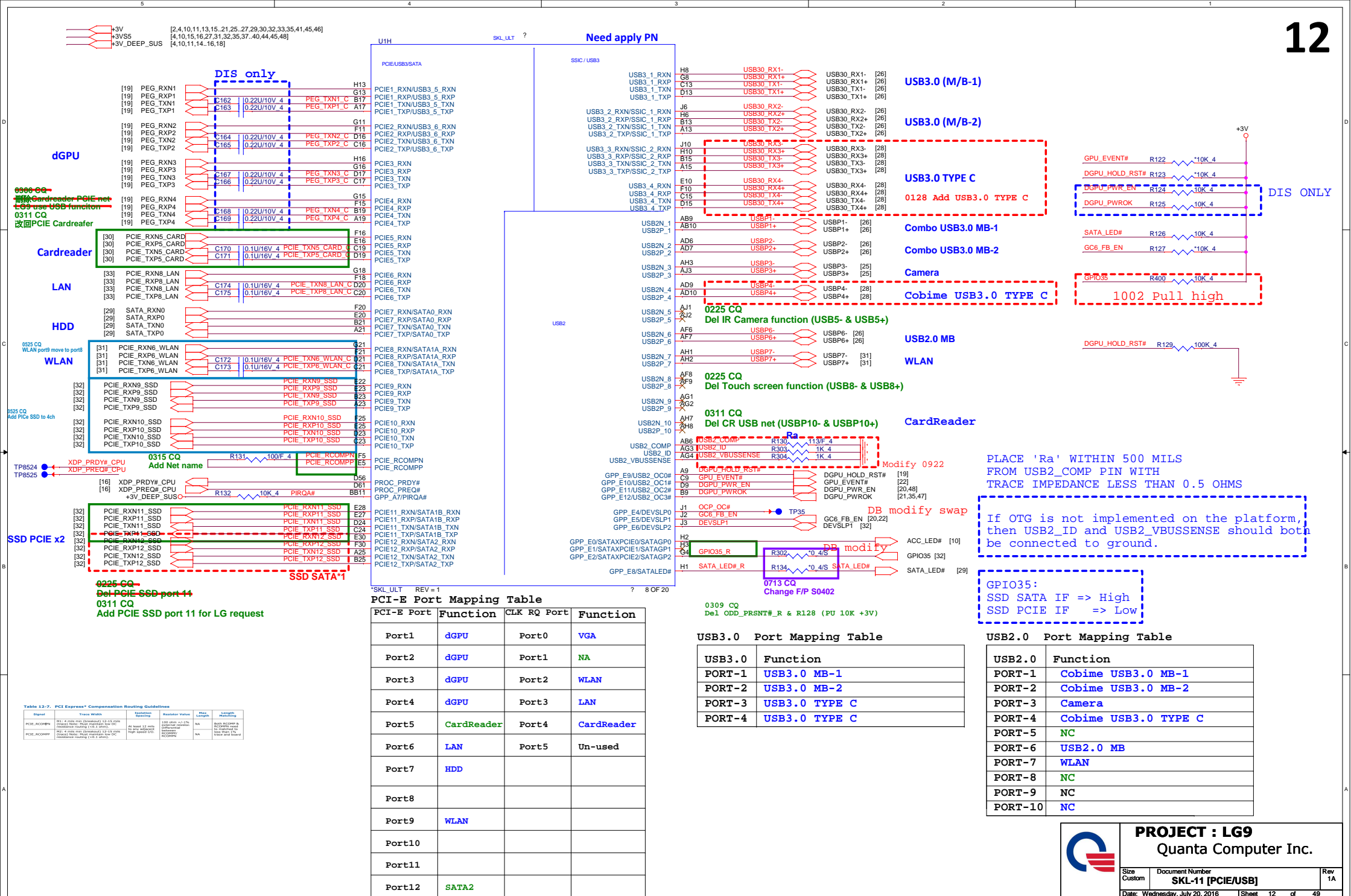


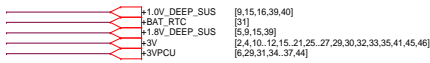
No Boot:
The signal has a weak internal pull-down.
0 = Disable No Reboot mode.
1 = Enable No Reboot mode (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/XDP.



No Boot:
The signal has a weak internal pull-down.
0 = LPC is selected for EC.
1 = eSPI is selected for EC.

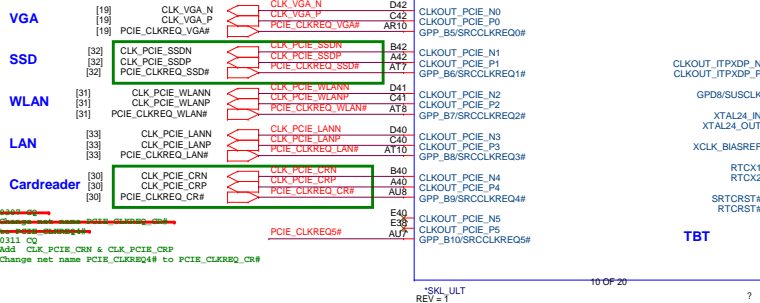
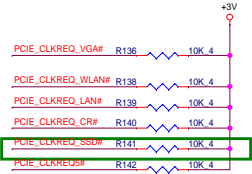






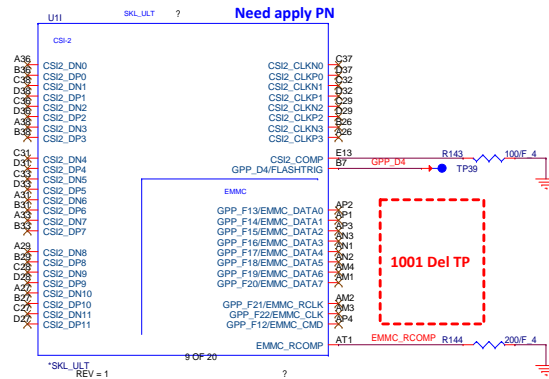
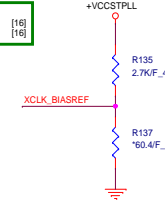
```
0226 CQ
Del CLK_PCIE_SSDN & CLK_PCIE_SSDP
Change net name PCIE_CLKREQ_SSD# to PCIE_CLKREQI#
0311 CQ
Add CLK_PCIE_SSDN & CLK_PCIE_SSDP for LG request
Change net name PCIE_CLKREQI# to PCIE_CLKREQ_SSD#
```

CLK_REQ/Strap Pin(CLG)



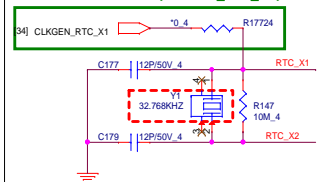
0305 CQ
Change net name
CK_XDP_N_R to CK_XDP_N
CK_XDP_P_R to CK_XDP_P
0307 CQ
Add 0 ohm contact to page16 xDP
XDP_N & XDP_P
Del TP

1027 modify for eazy layout

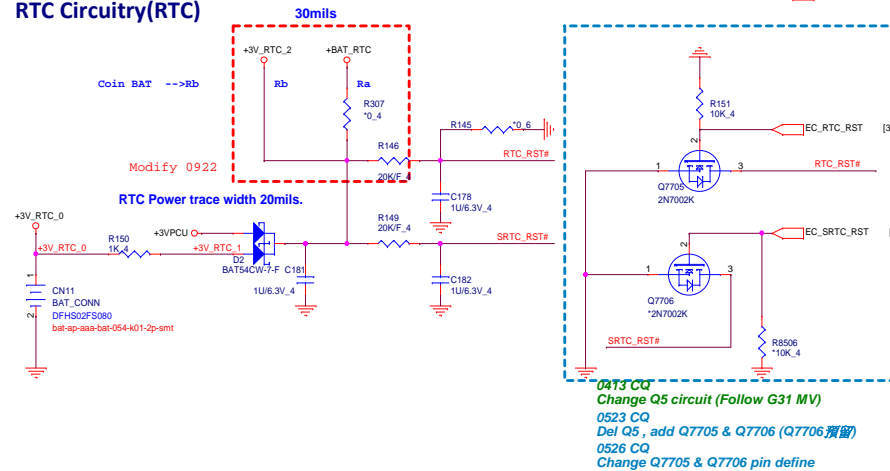


RTC Clock 32.768KHz

0301 CQ
Add GCLK XTALIN (CLKGEN_RTC_X1) & 0ohm

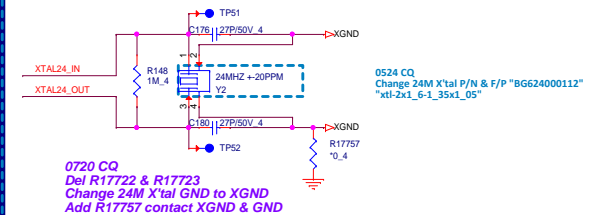


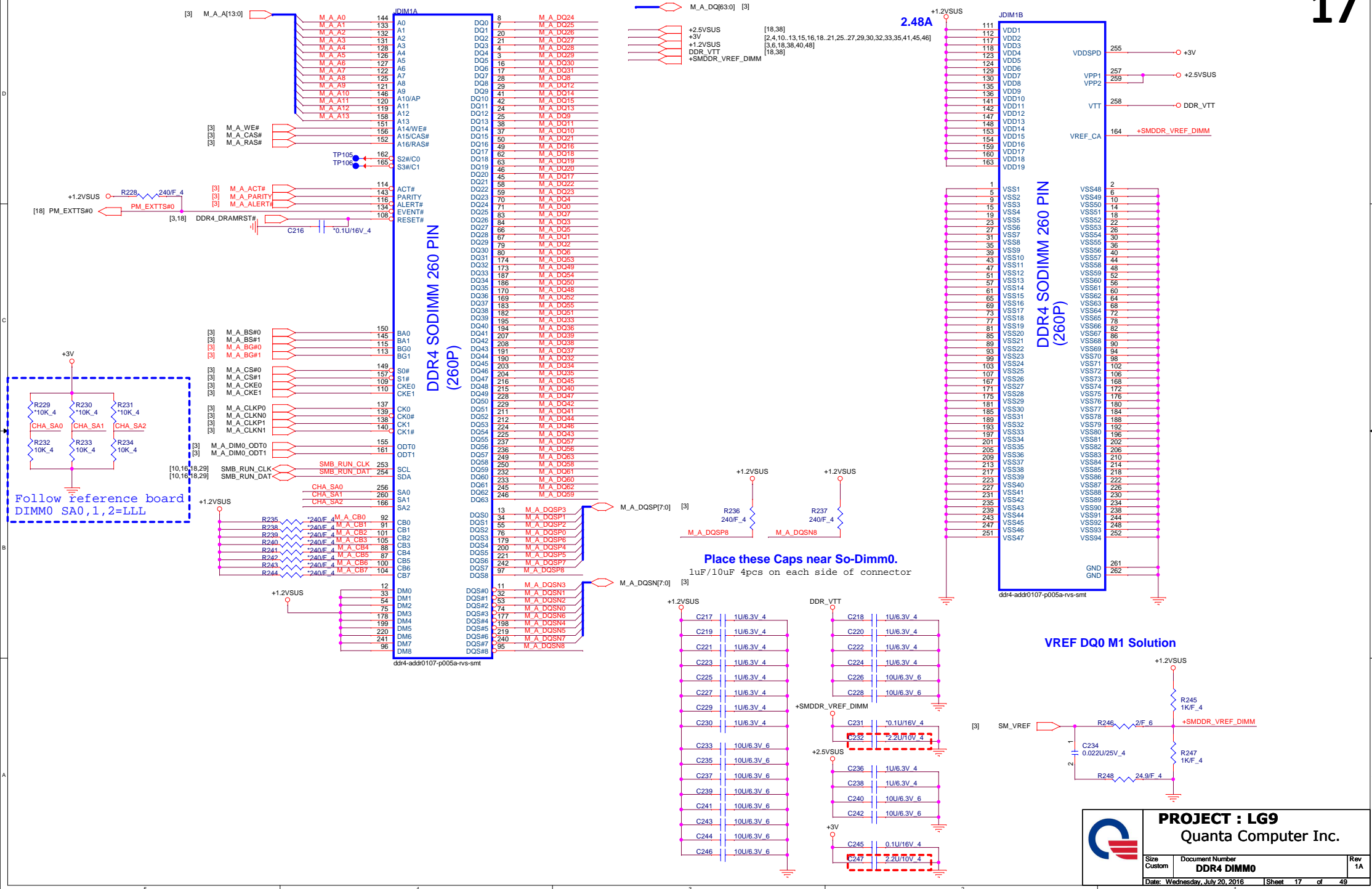
RTC Circuitry(RTC)



External Crystal

The 24 MHz (50 Ohm ESR) XTAL used for Skylake-U needs to be replaced by 38.4 MHz (30 Ohm ESR) XTAL for Cannonlake-U.





PEX_IOVDD + PEX_IOVDDQ = 1.042A

PEX_PLL_HVDD +
PEX_SVDD_3V3 = 143mA

PEX_PLLVDD = 130mA

if stuff Da,Db,Ra,Rb
do not stuff Ua,Ub,Ca,Cb,Rc,Rd

- PEX_TSTCLK_OUT should be terminated with PEX_TSTCLK_OUT# using a 200 Ω resistor and made easily accessible for probing; default can be unstuffed.

17.2 TEST MODE

By default, pull-down the TESTMODE pin to GND with a 10 k Ω resistor. For ICT/boundary scan requirements, contact your NVIDIA AE.

- PEX_TERMP is used for internal calibration; pull-down this signal with a 2.49 k Ω , 1% resistor.

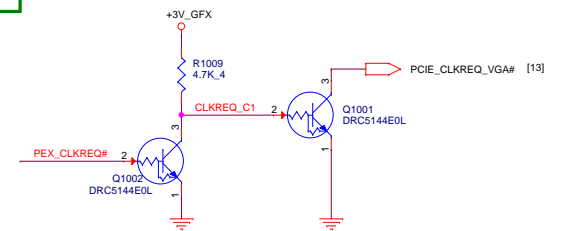
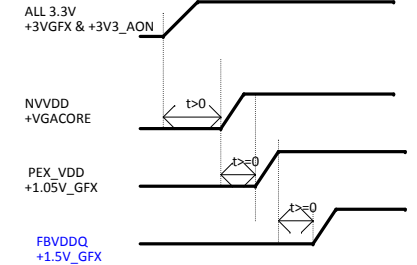
[20,21,48]
[21,22,46,48]
[22,34,48]
[20,23,24,47]
[20,32,33,35,41,45,46]
[46]

+1.05V_GFX
+3V_GFX
+3V_AON
+1.5V_GFX
+3V
+VGACORE

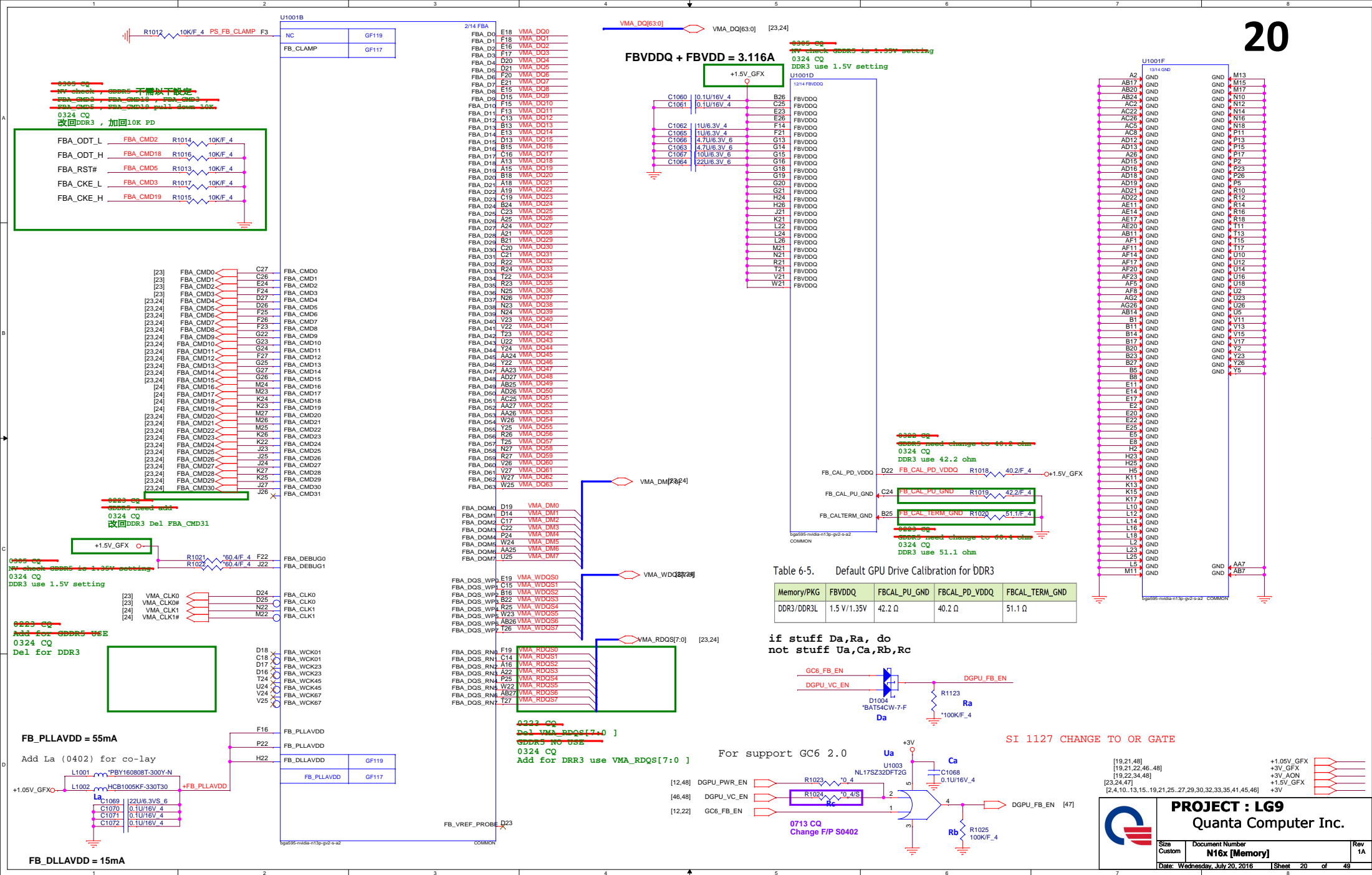
NVDD = 32.22 ~ 26.66 A +VGACORE

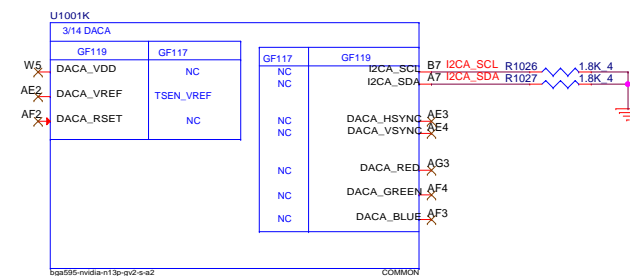
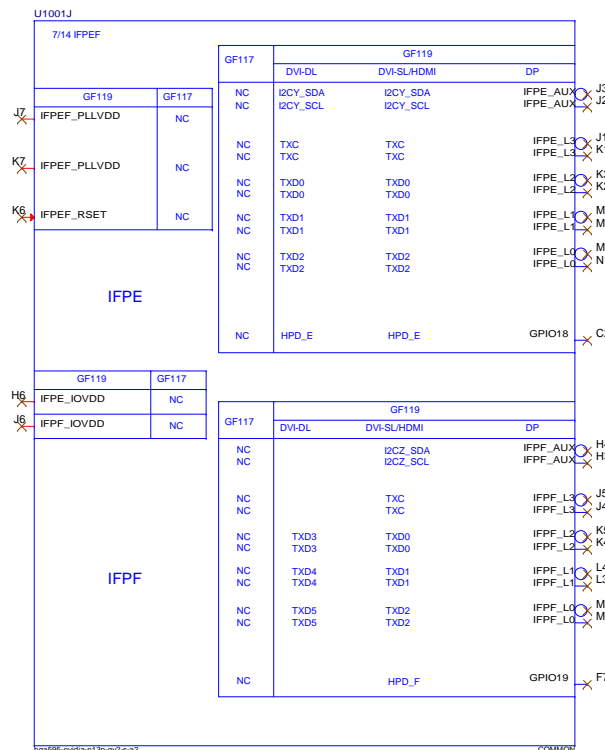
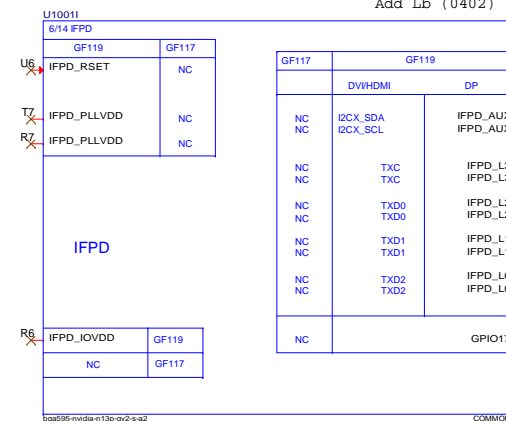
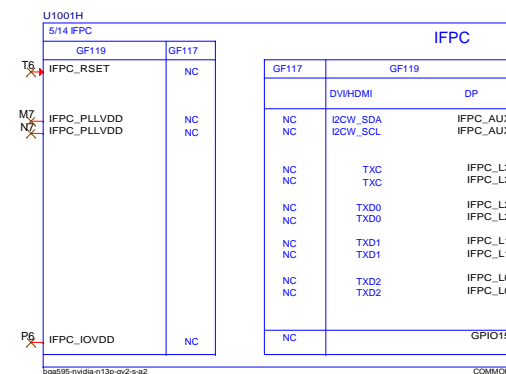
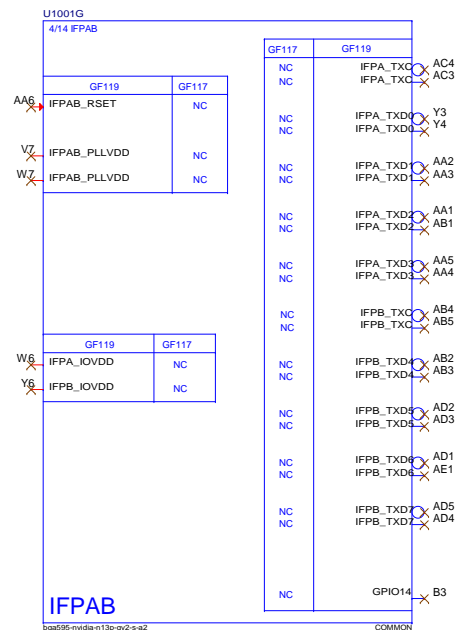
VDD33 = 56mA

Power up sequence

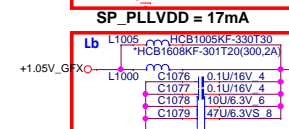


	PROJECT : LG9		
	Quanta Computer Inc.		
Size Custom	Document Number N16x [PCIE]	Rev 1A	
Date: Wednesday, July 20, 2016	1 Sheet	19 of 49	

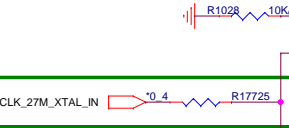




PLLVDD = 38mA
Add Ia (0402) for co-layer



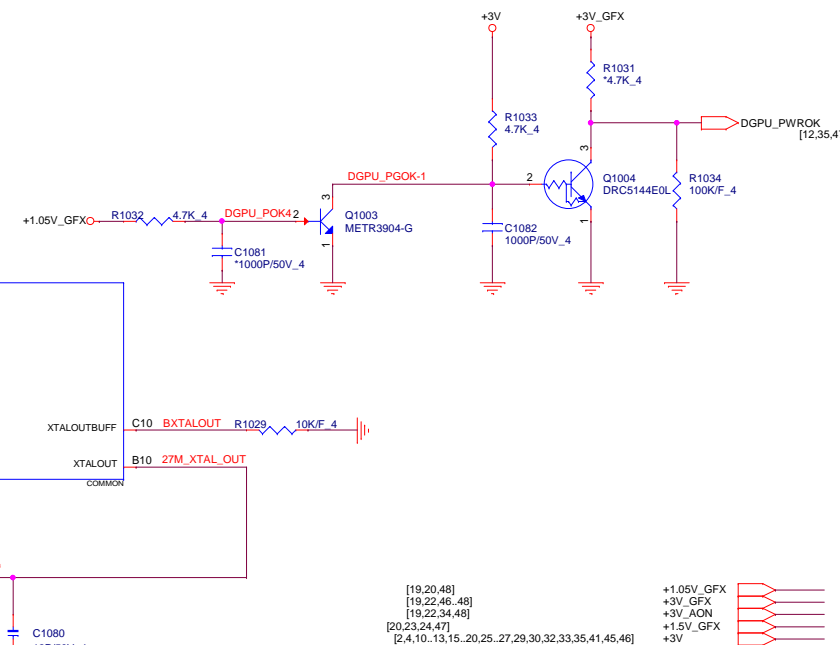
VID_PLLVDD = 41mA



0301 CQ
Add GCLK XTALIN (CLK_27M_XTAL_IN) & 0ohm

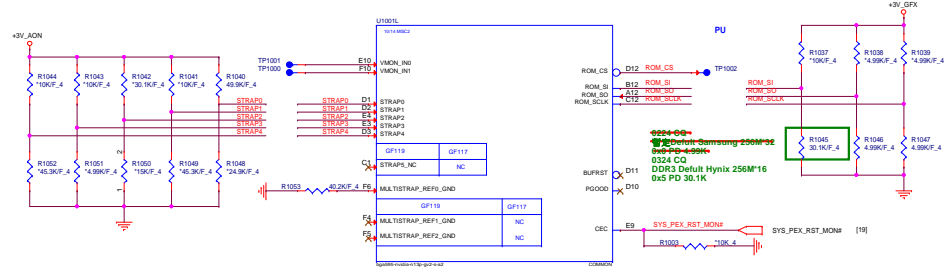


1223 change cap to 12P

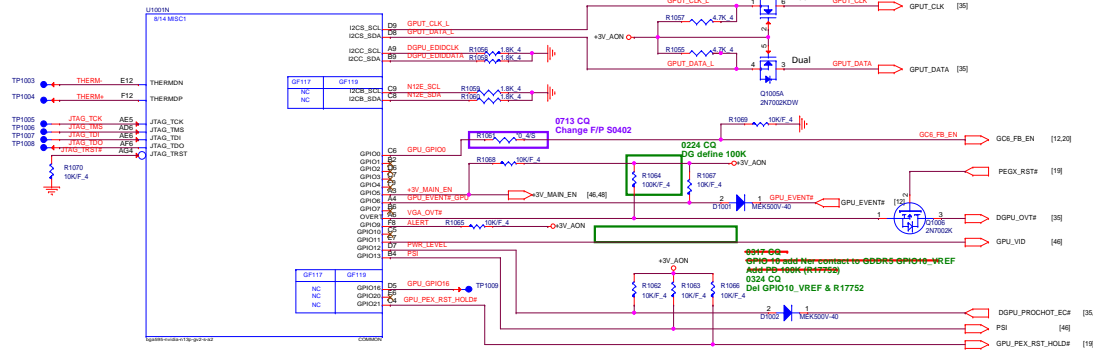


[19,20,48]
[19,22,46,48]
[20,23,24,47]
[2,4,10,13,15,20,25,27,29,30,32,33,35,41,45,46]

+1.05V_GFX
+3V_GFX
+3V_AON
+1.5V_GFX
+3V



GPU STRAP	N16S-GTR/ N16V-GMR1
ROM_SI	RVL
ROM_SO	PD 4.99kΩ
ROM_SCLK	PD 4.99kΩ
STRAP0	PU 49.9kΩ
STRAP1	NU
STRAP2	NU
STRAP3	NU
STRAP4	NU



SIZE	Vendor	Quanta P/N	Mfr. P/N
128Mx16	Samsung	AKD5M9T502	K4W2G63FR-BC1A
256Mx16	Samsung	AKD5P2DTW00	H5TC4G63CFR-BC1A

4.99k	CS2492P026
10k	CS1310P026
15k	CS1310P026
20k	CS1310P026
24.9k	CS1310P026
30.1k	CS1310P026
34.8k	CS1310P026
45.3k	CS1310P026

Table 12-2. GB2B-64 and GB4B-128 GPIO Description

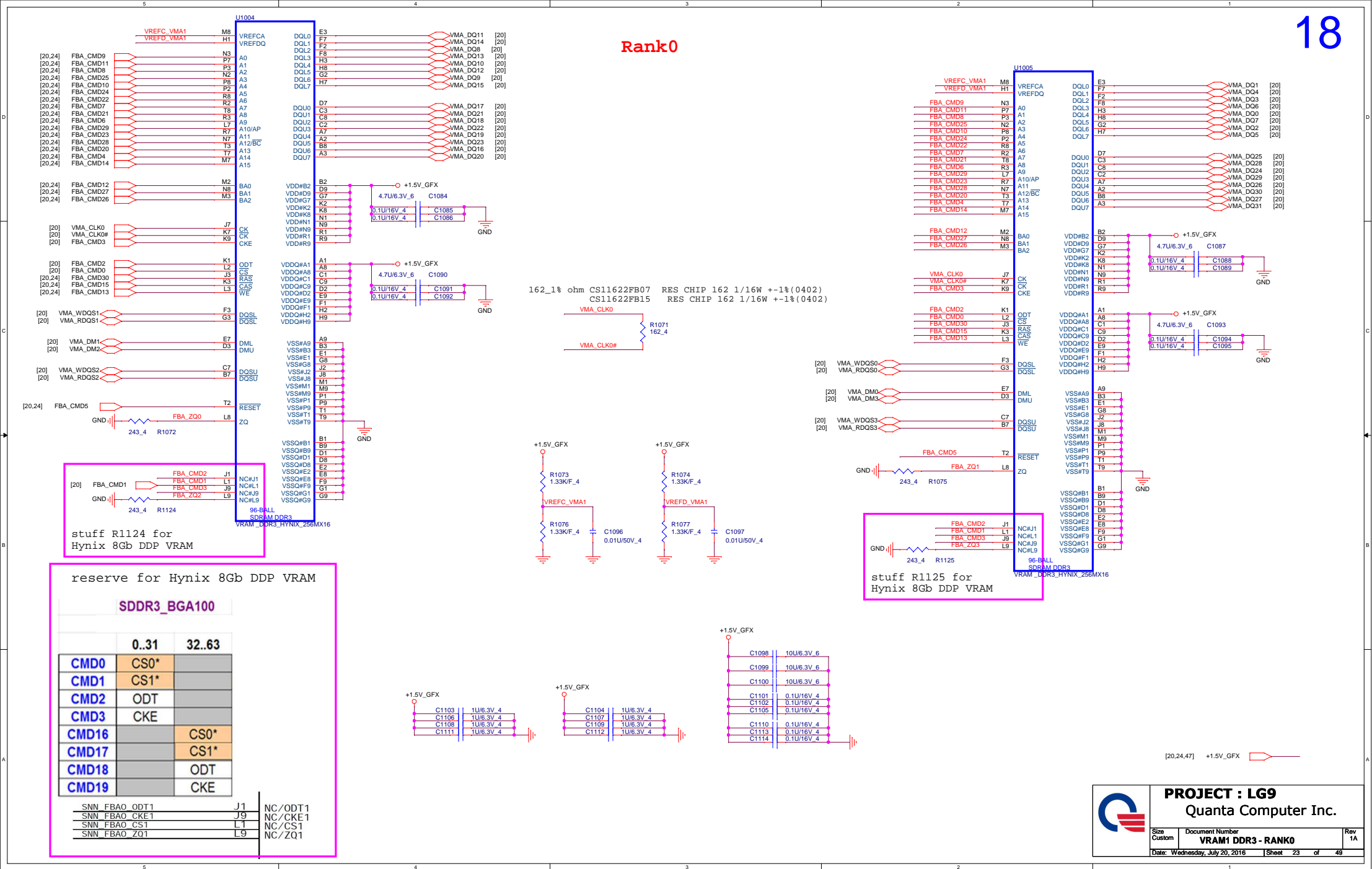
GPIO Number	GPIO Name	I/O	Functional Description	I/O Termination
GPIO0	GC6_FB_EN	O	FB Enable for GC6 2.0, Open Source	10 kΩ pull-down
GPIO1	MEM_VDD_CTL	O	Memory voltage control	Pull-up/pull-down to set the FBVDD/Q boot voltage
GPIO2	LCD_BL_PWM	O	Panel Backlight PWM Brightness Control	100 kΩ pull-down
GPIO3	LCD_VCC	O	Panel Power Enable	100 kΩ pull-down
GPIO4	LCD_BLEN	O	Panel Backlight Enable	100 kΩ pull-down
GPIO5	3V3_MAIN_EN	O	GPU power sequencing for GC6 2.0, Open Drain	10 kΩ pull-up to 3V3_AON
GPIO6	GPU_EVENT#	I	GPU wake signal for GC6 2.0	10 kΩ pull-up to 3V3_AON
GPIO7	3Dvision	O	3D Vision L/R signal	100 kΩ pull-down
GPIO8	SYS_PEX_RST_MON#	I	System side PCIe reset monitor	10 kΩ pull-up to 3V3_AON unless actively driven
GPIO9	THERM_ALERT	I/O	Active Low Thermal Alert, Open Drain	10 kΩ pull-up to 3V3_AON
GPIO10	MEM_VREF_CTL	O	Memory VREF Control	100 kΩ pull-down
GPIO11	PWM_VID	O	GPU Core VDD PWM control signal	
GPIO12	PWR_LEVEL	I	AC power detect or power supply overdraw input	100 kΩ pull-up to 3V3_AON
GPIO13	PSI	O	Phase Shedding	10k pull-up to 3V3_AON to enable two phase.
GPIO14	HPD_A	I	Hot Plug Detect for IFPA used as DisplayPort or for IFPAB when used as Dual Link DVI	See Figure 12-1
GPIO15	HPD_C	I	Hot Plug Detect for IFPC	See Figure 12-1
GPIO16	FRAME_LOCK#	I	Active Low Frame Lock, Open Drain	10 kΩ pull-up to 3V3_AON; Not available for GB2B-64
GPIO17	HPD_D	I	Hot Plug Detect for IFPD	See Figure 12-1
GPIO18	HPD_E	I	Hot Plug Detect for IFPE	See Figure 12-1
GPIO19	HPD_F or HPD_B	I	Hot Plug Detect for IFPF or for IFPB when used as DisplayPort	See Figure 12-1
GPIO20	Reserved			
GPIO21	GPU_PEX_RST_HOLD#	O	GPU PCIe self-reset control, Open Drain	10 kΩ pull-up to 3V3_AON
OVERT	OVERT	I/O	Catastrophic Over Temperature	100 kΩ pull-up to 3V3_AON

Table 13. N16V-GMR1 and N16S-GMR1/-GTR DDR3 Recommended Memories

Memory Type	FBVDD/ FBVDDQ	Memory Density	Configuration	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed CK Grade(MHz)	Memory Date Code Minimum	Status
DDR3	1.5V/ 1.5V	128Mx16	Single Rank or Single Rank Stuffling for Dual Rank	Hynix	H5TC4G63FR-11C	F-die	Ox6	1000	N/A	Production ready
				Micron	MT41J128M16JT-093G-K	K-die	Ox7	1000	1322	Production ready
				Samsung	K4W2G1646Q-BC1A	Q-die	Ox8	1000	N/A	Production ready
			Single Rank or Single Rank Stuffling for Dual Rank	Hynix	H5TC4G63AFR-11C	A-die	Ox0	1000	N/A	Production ready
				Micron	MT41J256M16HA-093G-E	E-die	Ox1	1000	1322	Production ready
				Samsung	K4W4G1646D-BC1A	D-die	Ox2	1000	N/A	Production ready
		256Mx16	Single Rank or Single Rank Stuffling for Dual Rank	Samsung	K4W4G1646E-BC1A	E-die	Ox4	1000	N/A	Production ready
				Hynix	H5TC4G63CFR-H0C	C-die	Ox5	1000	N/A	Production ready
				Micron	MT41J256M16LY-091G-H	H-die	Ox3	1000	N/A	Post-production candidate
			Dual Rank	Hynix	H5TC4G63AFR-11C	A-die	Ox0	1000	N/A	Production ready
				Micron	MT41J256M16HA-093G-E	E-die	Ox1	1000	1322	Production ready
				Samsung	K4W4G1646D-BC1A	D-die	Ox2	1000	N/A	Production ready
Dual Rank	Samsung	K4W4G1646E-BC1A	E-die	Ox0	1000	N/A	Production ready			
	Hynix	H5TC4G63CFR-H0C	C-die	Ox6	1000	N/A	Production ready			
	Micron	MT41J256M16LY-091G-H	H-die	Ox7	1000	N/A	Post-production candidate			

Table 15-2. Resistance Mapping to Hex Values

Resistor Values	Pull-Up to 3V3_MAIN	Pull-Down to GND
4.99 kΩ	1000	0000
10.0 kΩ	1001	0001
15.0 kΩ	1010	0010
20.0 kΩ	1011	0011
24.9 kΩ	1100	0100
30.1 kΩ	1101	0101
34.8 kΩ	1110	0110
45.3 kΩ	1111	0111

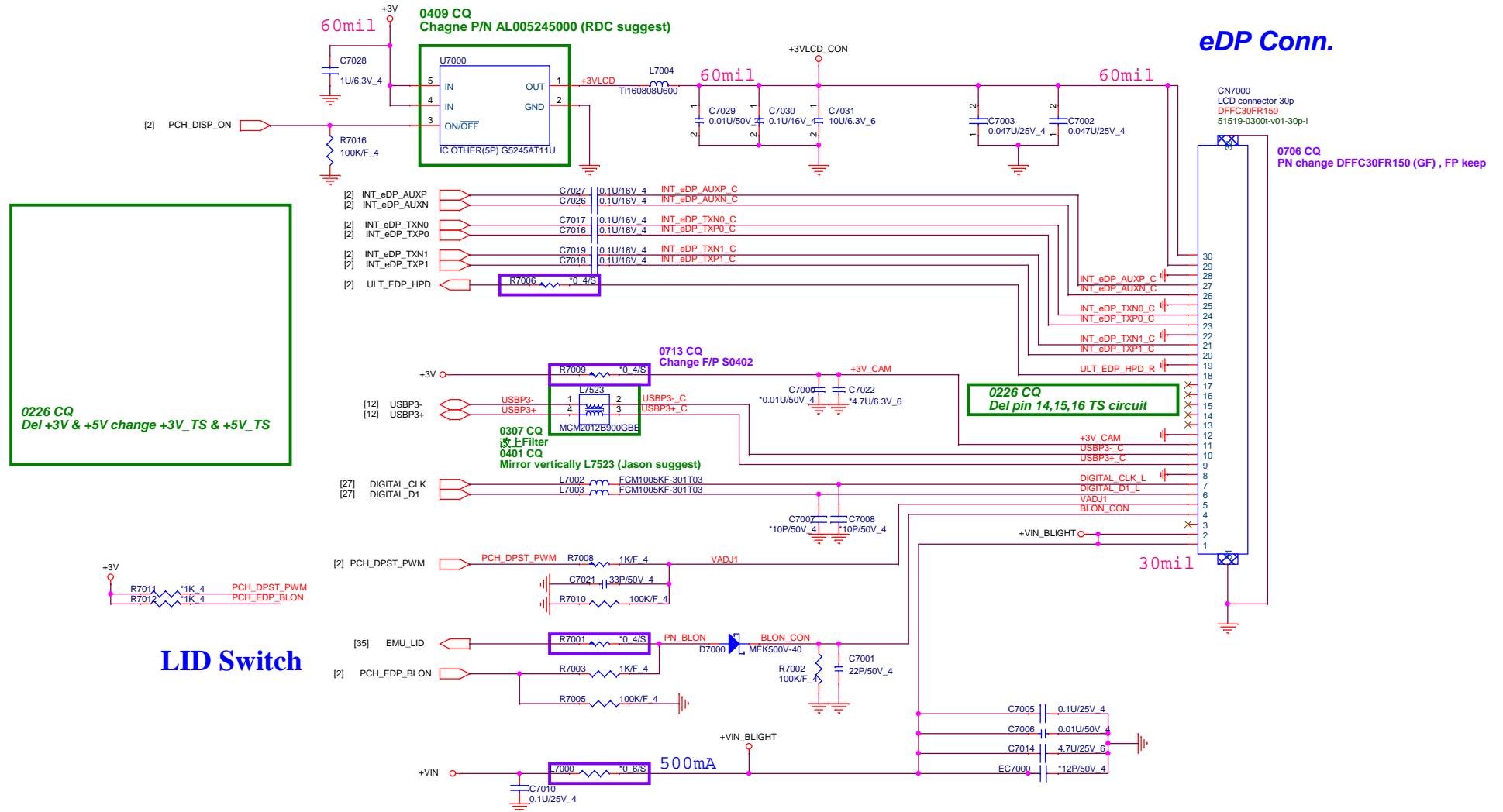




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Size Custom	Document Number VRAM2 DDR3 - RANK0	Rev 1A
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0219 CQ Re-draw & Compare OK



[4,10,15,16,27,31,32,35,37,40,44,45,48]
[4,26,32,37,43,45,48]
[2,4,10,13,15,21,26,27,29,30,32,33,35,41,45,46]
[6,13,29,31,34,37,44]
[26,27,29,45]
[36,39,41,44,46,47,49]

+3V_CAM
+3VS5
+5VS5
+3V
+3VPCU
+5V
+VIN

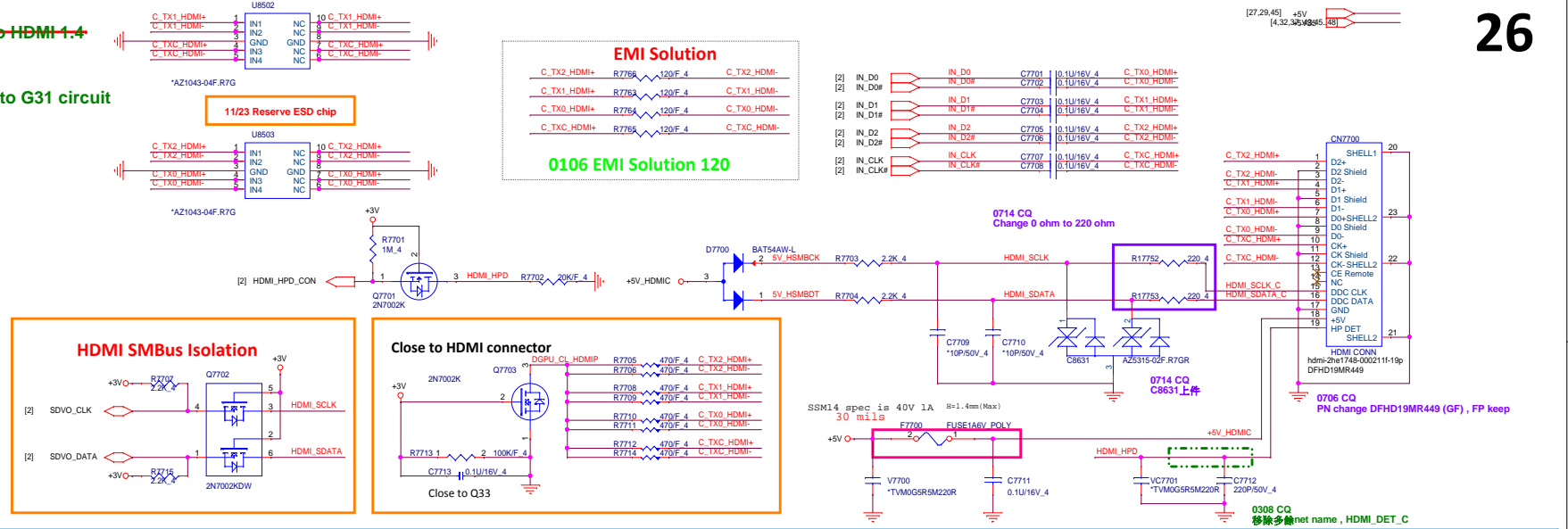


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Quanta Computer Inc.

Size	Document Number	Rev
Custom	eDP	1A
Date: Wednesday, July 20, 2016	Sheet 25 of 49	

~~0301 CQ~~
~~Del HDMI 2.0 circuit , Change to HDMI 1.4~~
~~Use TWL circuit~~

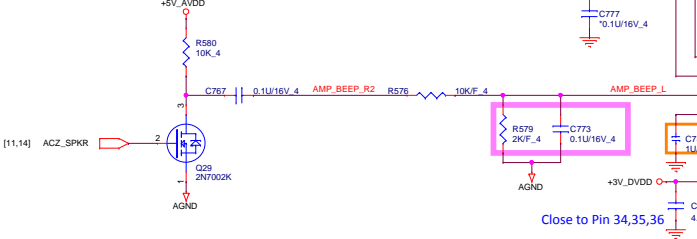
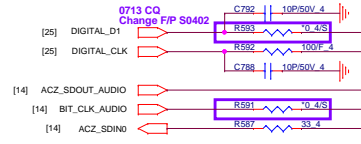
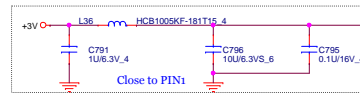
0305 CQ
 Del TWL HDMI circuit , change to G31 circuit



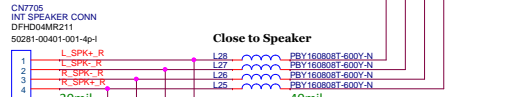
0318 CQ
 Add USB2.0 circuit



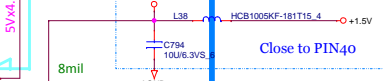
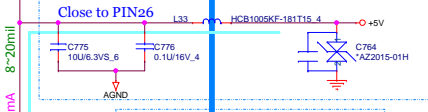
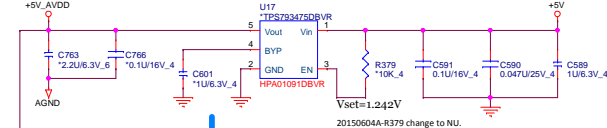
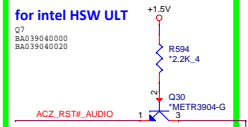
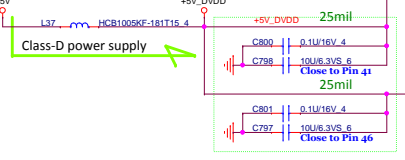
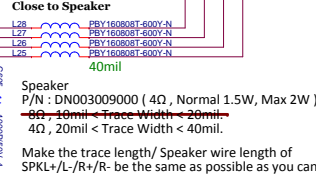
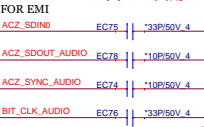
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INT. Speaker



0330 CQ
PN DFHD04MR211
與FAN共用

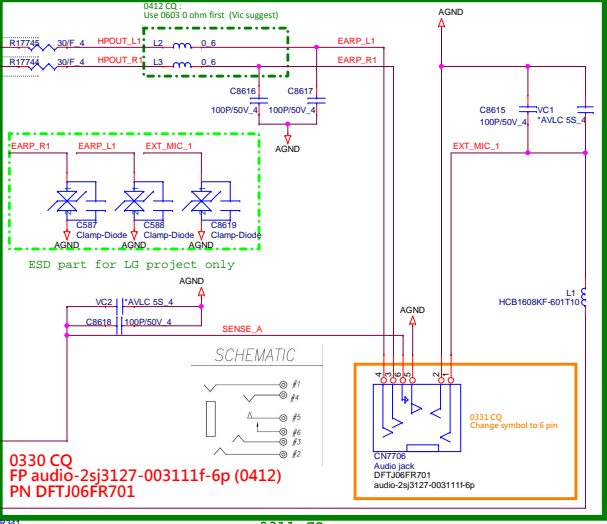


20150216A-
AVDD2 must connect with +1.5V
so cancel power source of +3V.



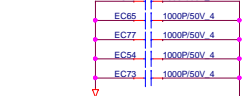
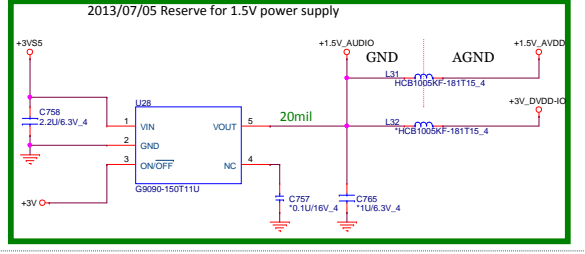
0319 CQ :
Change MIC_R1 from PIN 20 to PIN 18 for ALC255-CG suggest
Change MIC_L1 from PIN 19 to PIN 17 for ALC255-CG suggest
Change VREFOUT_C from PIN 31 to PIN 29 for ALC255-CG suggest

AUDIO COMBO JACK

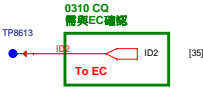
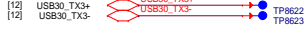
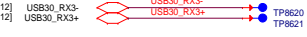
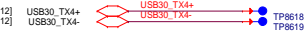
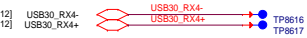
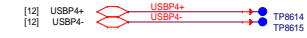


0330 CQ
FP audio-2sj3127-003111f-6p (0412)
PN DFTJ06FR701

~~0311 CQ~~
~~CardReader 改回 PCIE type~~
~~Connector 改成 40pin~~
~~0316 CQ~~
~~Reversion 2D Conn pin Define (board request)~~
0316 CQ
取消小板！將Audio Jack加回



place to near Audio Chip or under Audio Chip.

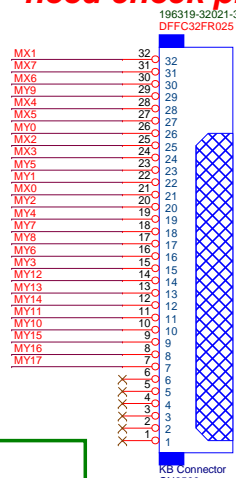


0412 CQ
刪除TypeC線路，保留USB & ID2 線段

KEYBOARD Con.

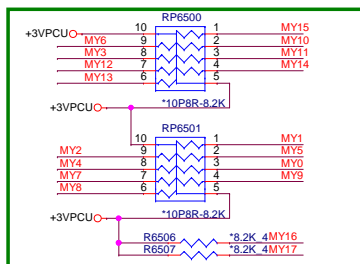
[35] MY[0..17]  MY[0..17]
[35] MX[0..7]  MX[0..7]

need check pin define

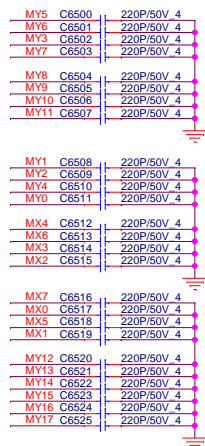


0307 CQ
Del CAPSLED# & MUTE_LED_CNTL cricuit
(Use TWL KB)
0411 Dennis
Swap KB Pin define for ME request

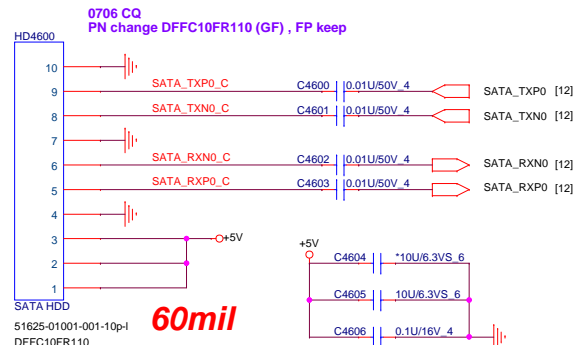
KEYBOARD PULL-UP



0406 CQ
Swap pin for layout
0412 CQ
Swap pin for layout again



HDD



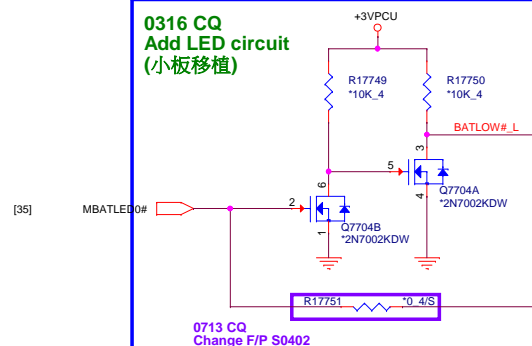
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[26,27,45]
[45]
[25]
[25,36,39,41,44,46,47,49]

+3V
+3VPCU
+5V
+3VSUS
+3V_CAM
+VIN

0307 CQ
刪除SATA LED雙色燈 circuit

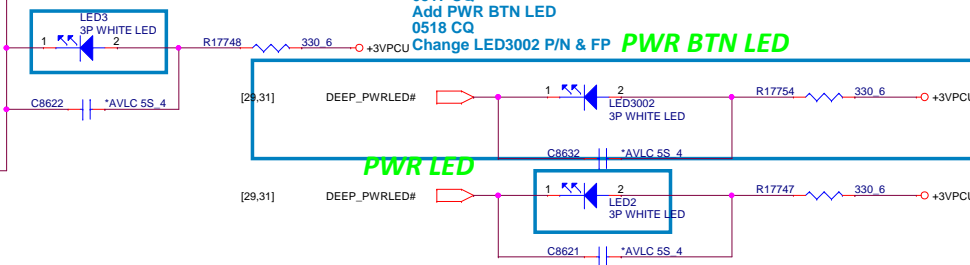
0226 CQ
Del IR CAM circuit

0316 CQ
Add LED circuit
(小板移植)



0508 CQ
Change LED1, LED2, LED3 F/P ledltw-110uc5-3p

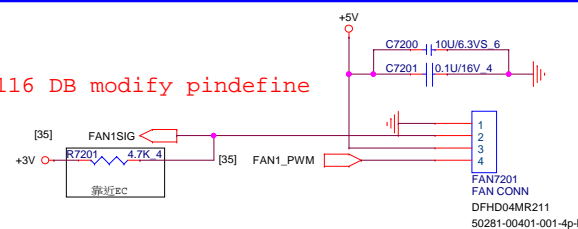
BAT LED



PWR LED

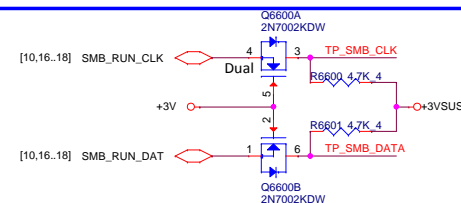
FAN

1116 DB modify pindefine

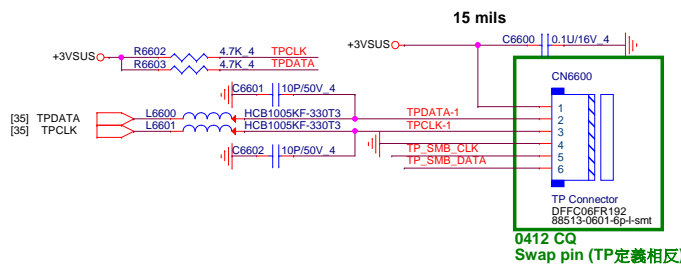


FAN1_PWM C7202 *220P/50V 4
FAN1SIG C7203 *220P/50V 4

0330 CQ
PN DFHD04MR211
FP 50281-00401-001-4p-I (0408)



Touch Pad Connector

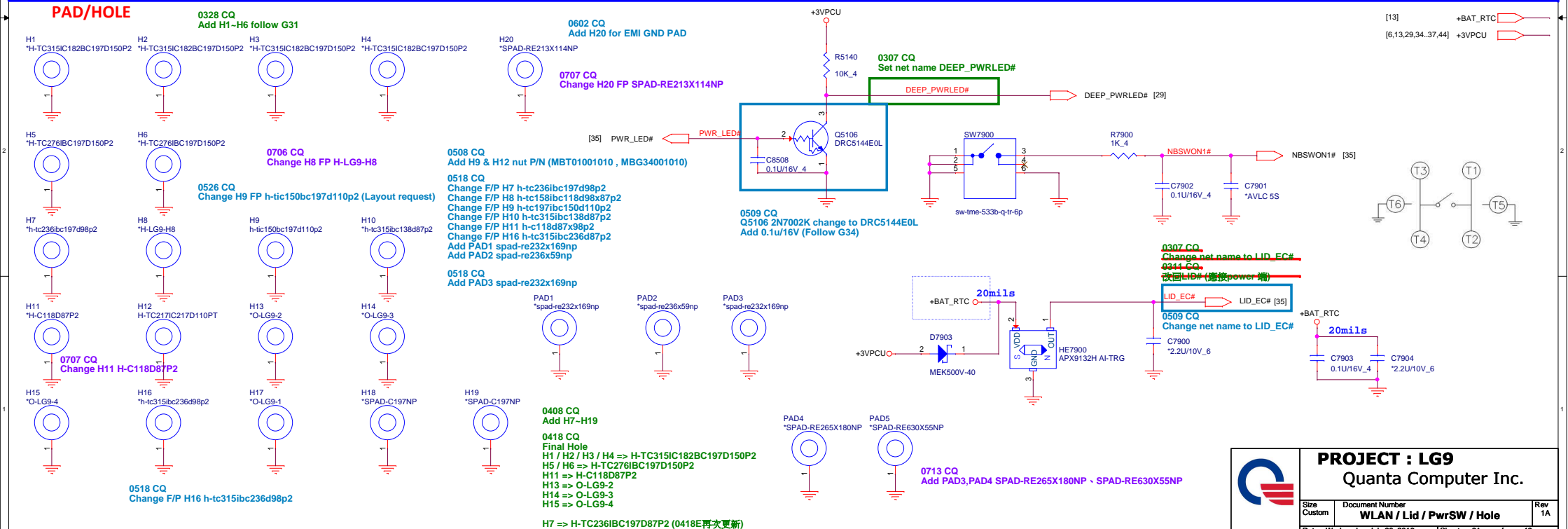


0412 CQ
Swap pin (TP定義相反)



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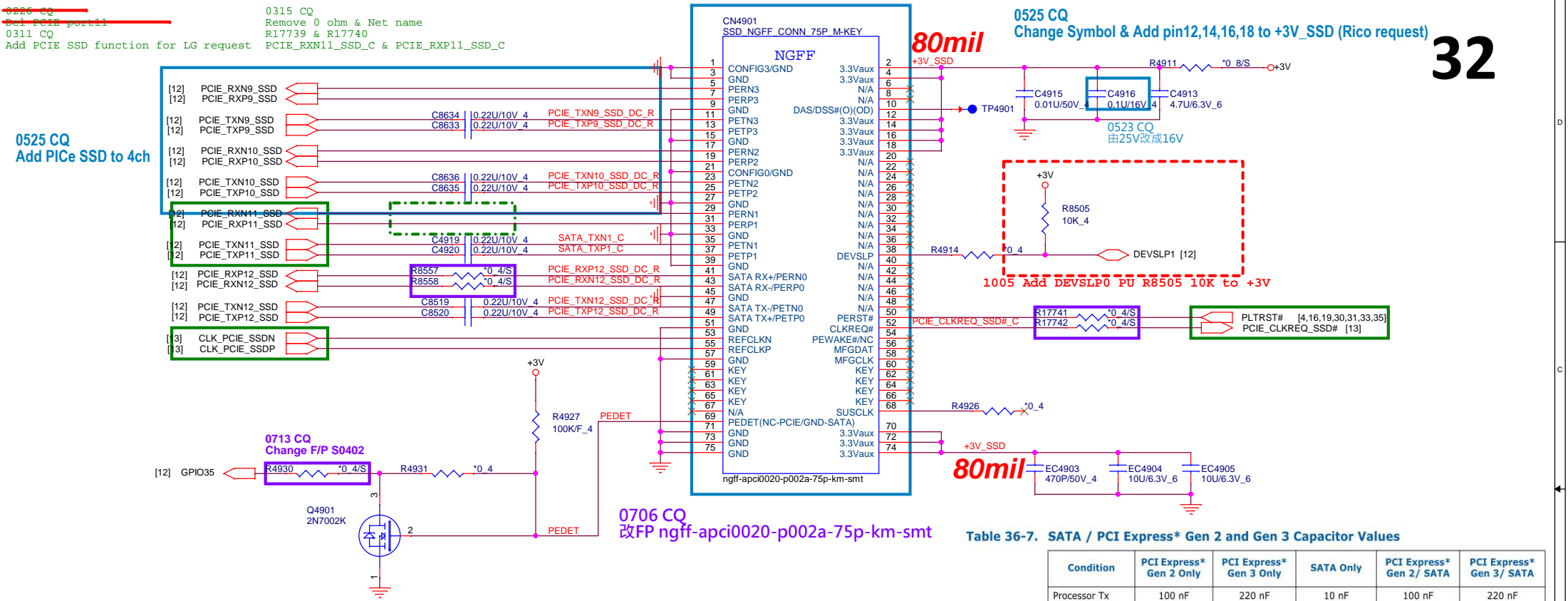
Size	Document Number	Rev
Custom	HDD/ TP / KB / FAN / LED	1A
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0226 CQ
Del PCIe port11
0311 CQ
Add PCIe SSD function for LG request

0315 CQ
Remove 0 ohm & Net name
R17739 & R17740
PCIe_RXN11_SSD_C & PCIe_RXP11_SSD_C

0525 CQ
Add PIce SSD to 4ch



32

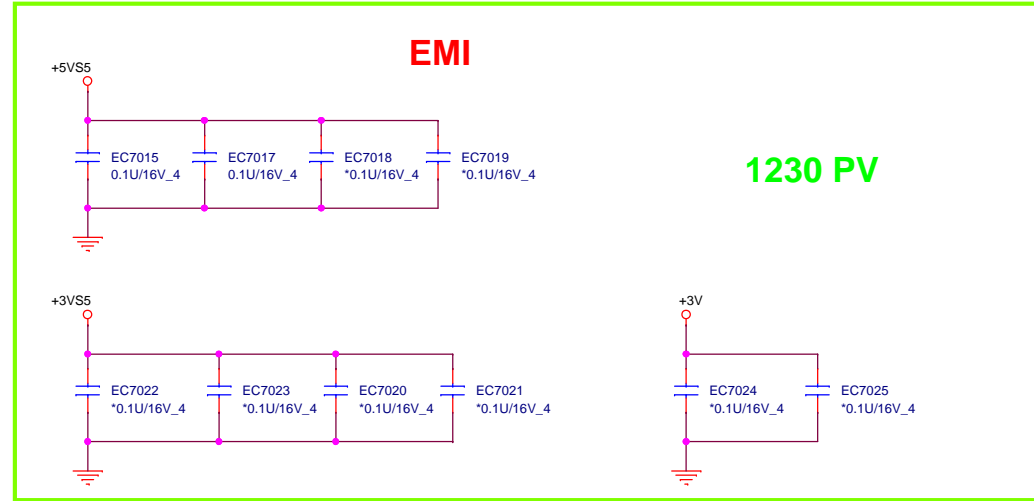


Table 36-7. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2/ SATA	PCI Express* Gen 3/ SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ²	None	None ³

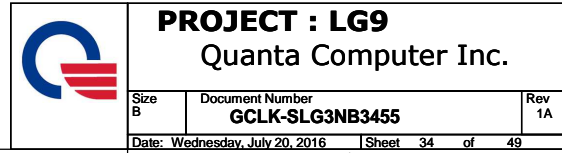
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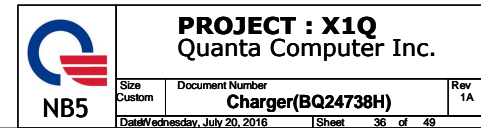
- Design Constraint: For PCIe only application, please refer to the PCIe guidelines for details.
- Design Constraint: For SATA only application, both Tx and Rx channels need to have 10 nF capacitors on the motherboard. This option supports all SATA devices. However, the 10 nF capacitor on Rx can be removed if DC coupled ODDs / devices are NOT used.
- Design Constraint: For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraint: For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraints, Required: Refer tChapter 3, "General Differential Signals Design Guidelines" " along with the additional guidelines in this section for all design optimization guidelines.
- Design Constraint: For PCIe* lane that needs to support either **PCIe* Gen2 devices** or **PCIe* Gen3 devices**, follow the PCIe* Gen 3/ SATA multiplexed configuration where the motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**

[2,4,10..13,15..21,25..27,29,30,33,35,41,45,46] +3V

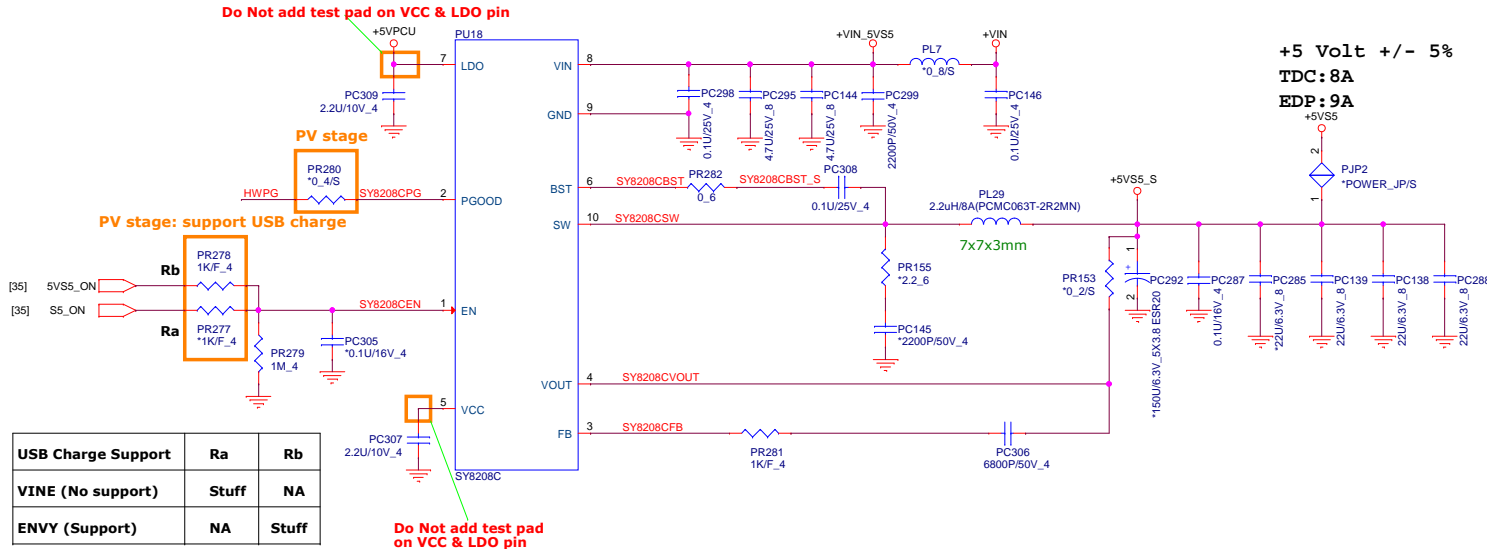
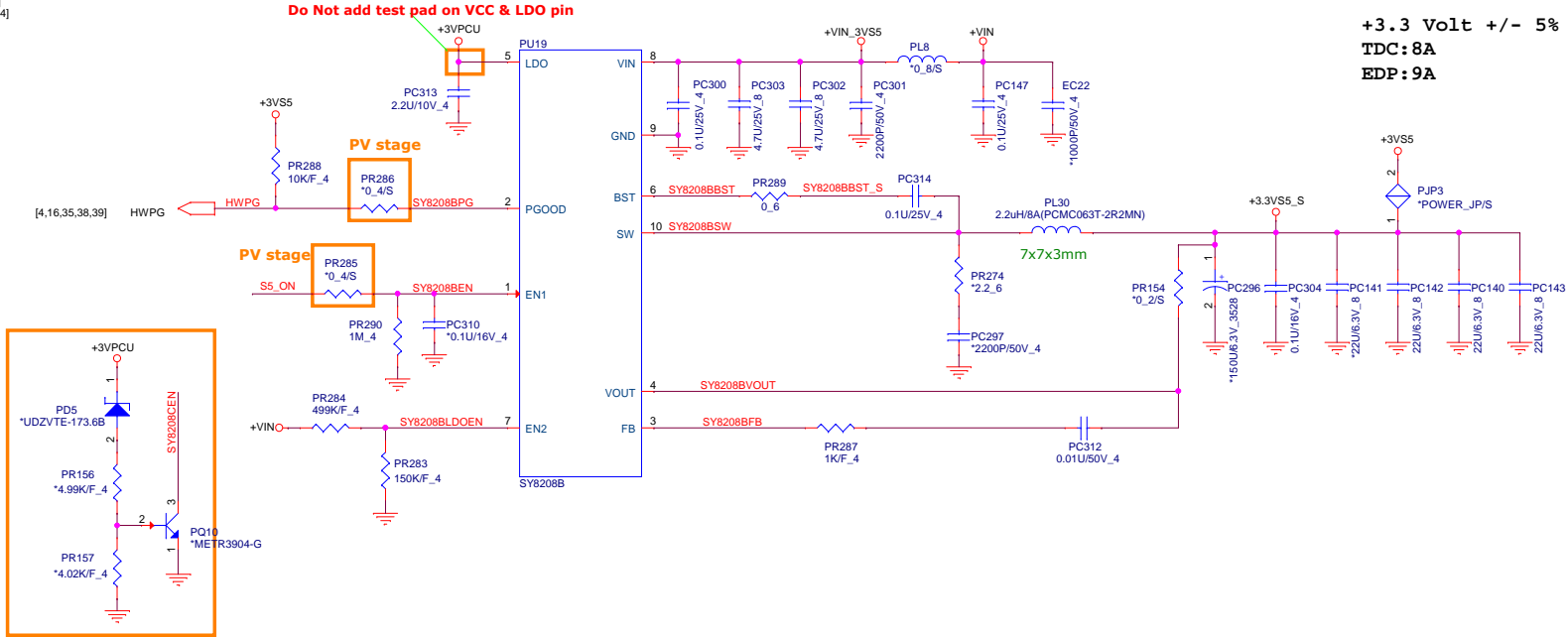
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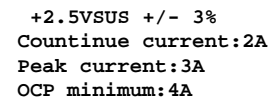
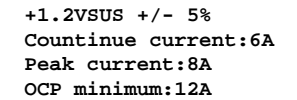
Size B	Document Number NGFF (PCIe/SATA)	Rev 1A
Date: Wednesday, July 20, 2016		Sheet 32 of 49



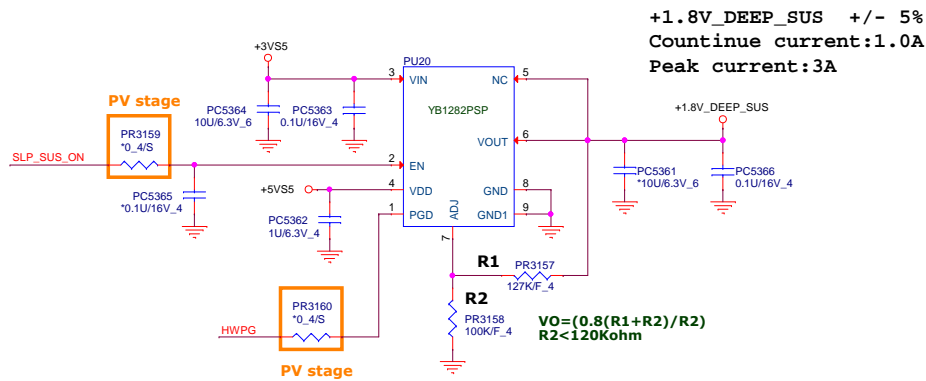
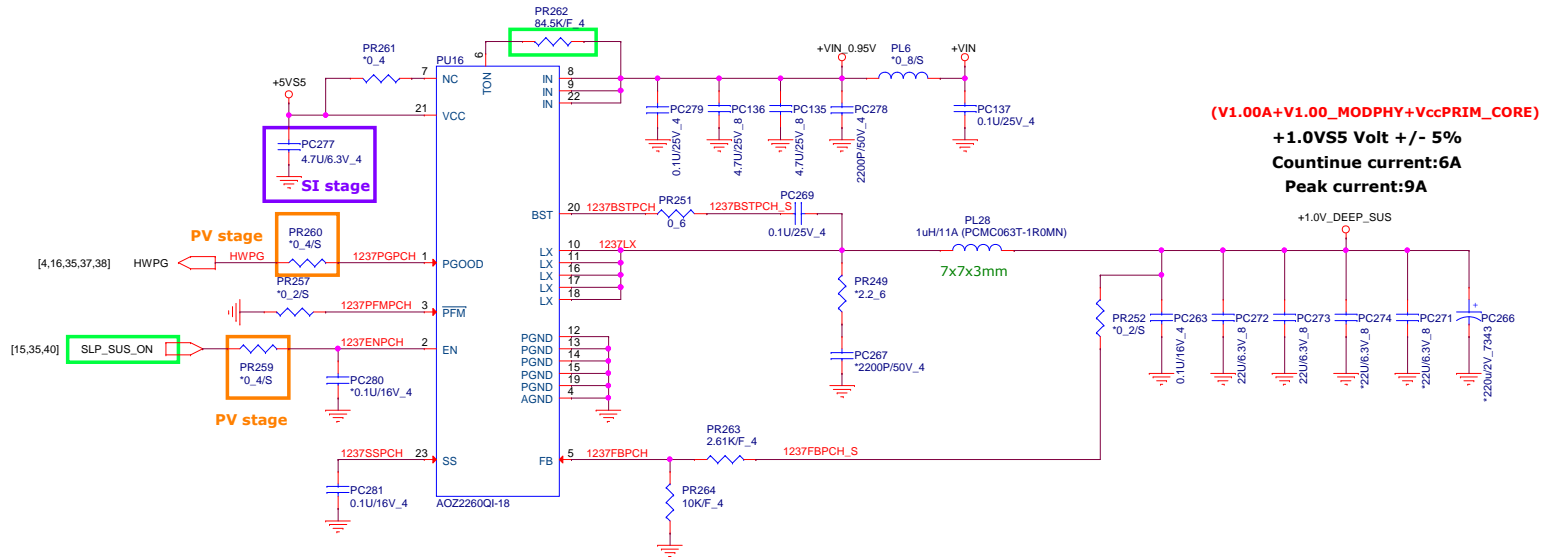


- +VIN [25,36,38,39,41..44,46,47,49]
- +3VS5 [4,10,15,16,27,31,32,35,38..40,44,45,48]
- +5VS5 [4,26,32,38..43,45,48]
- +3VPCU [6,13,29,31,34..36,44]
- +5VPCU [45,48]





+VIN [25,36,38,41,44,46,47,49]
 +3VS5 [4,10,15,16,27,31,32,35,37,38,40,44,45,48]
 +5VS5 [4,26,32,37,38,40,43,45,48]
 +1.0V_DEEP_SUS [9,15,16,40]
 +1.8V_DEEP_SUS [5,9,15]

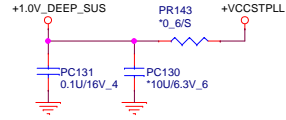


+1.0V	[2,4,6,16,34,35]
+3VSS	[4,10,15,16,27,31,32,35,37,39,44,45,48]
+5VSS	[4,26,32,37,39,41,43,45,48]
+VCCIO	[6,16]
+1.2VSUS	[3,6,17,18,38,48]
+VCCSTPLL	[2,4,6,9,13,41]
+1.0V_DEEP_SUS	[9,15,16,39]
+1.2V_VCCPLL_OC	[6]
MAINON	[26,35,38,40,45]

Volume Segment
Vcc_ST: 0.12A
Vcc_PLL: 0.12A

<= 10ms, full load ready
(Vcc_ST+Vcc_PLL)

Imax:0.24A



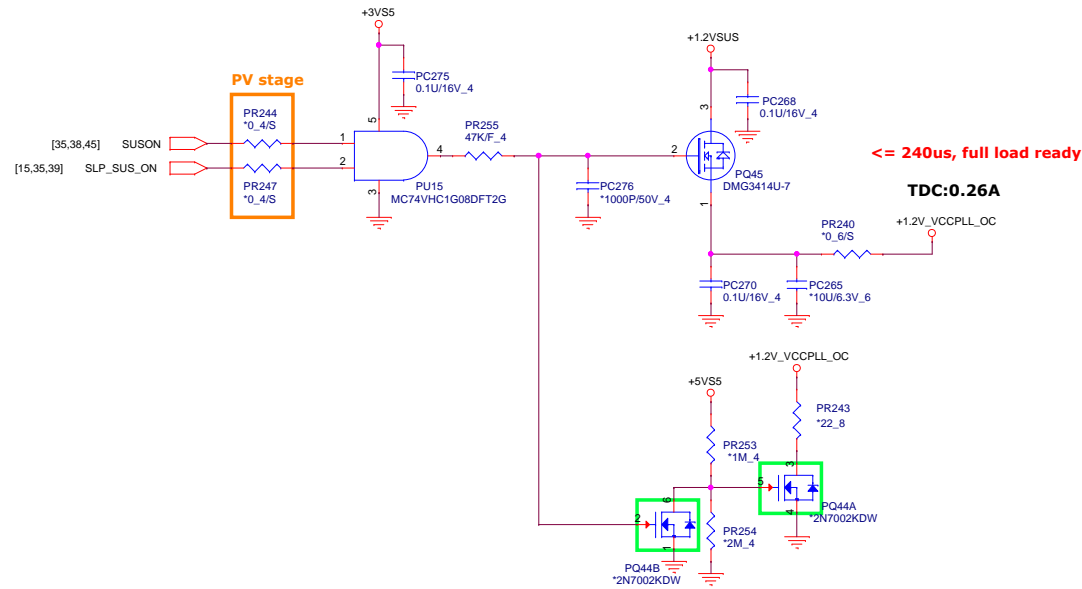
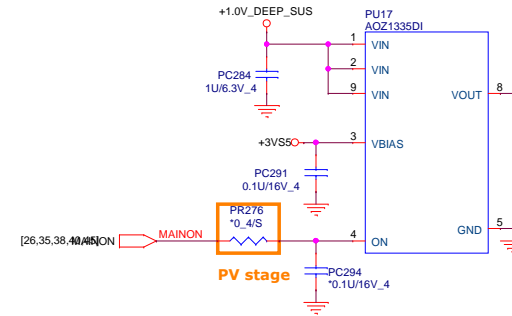
Volume Segment
Vcc_STG: 0.04A
Vcc_IO: 3.4A

<= 10ms full load ready

Imax:3.4A

Imax:0.04A

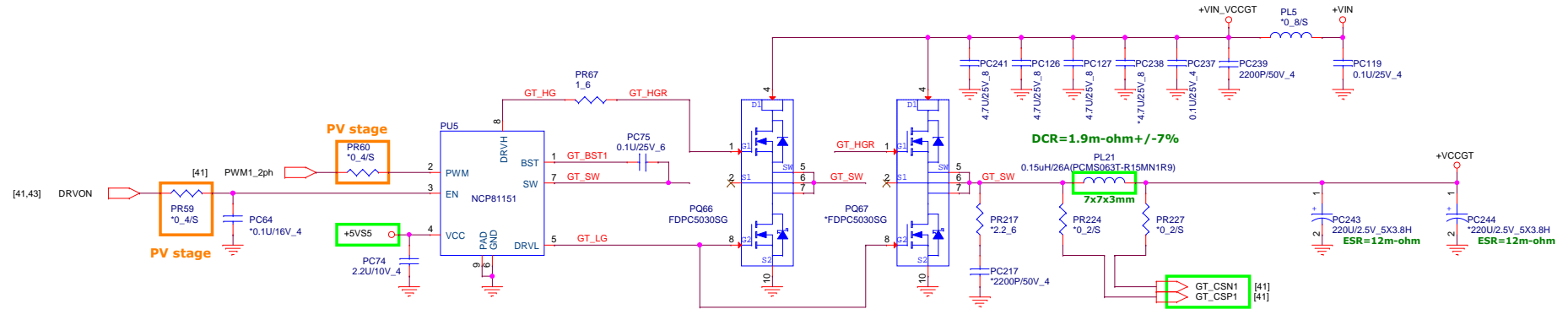
2015/10/26 updated



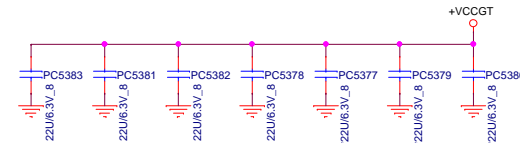
PROJECT : X1Q
Quanta Computer Inc.

Size	Document Number	Rev
Custom	+1.0V/+VCCSTPLL	1A
Date: Wednesday, July 20, 2016	Sheet 40 of 49	

+5V [26,27,29,45]
 +VIN [25,36,39,41,43,44,46,47,49]
 +5VPCU [37,45,48]
 +VCCGT [7,41]



For U23e --> Add These Components

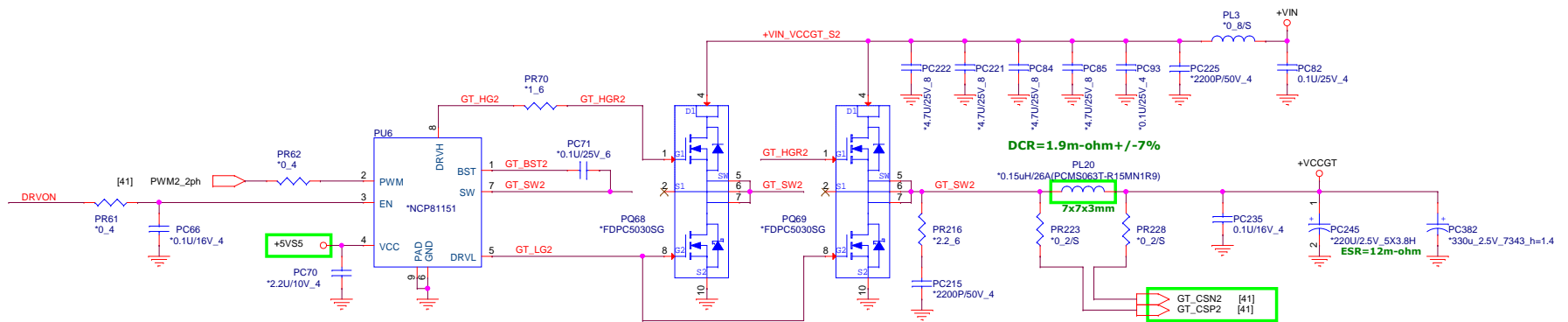


H/W side output CAP list

47U/6.3V_0805 X 6
 22U/6.3V_0603 X 12 (GTx+5)
 10U/6.3V_0402 X 10
 1U/6.3V_0402 X 12

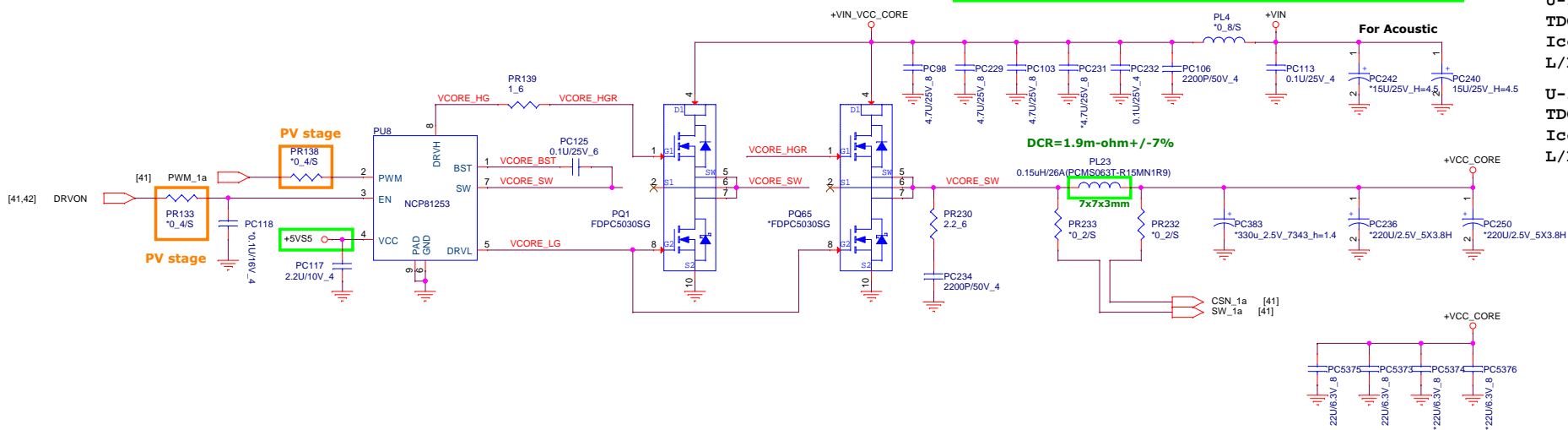
+VCCGT

U-line 22 (15W)
TDC:18A(22)
Icc max:31A(22)
L/L=3.1mV/A
U-line 23e(28W)
TDC:35A(23e)
Icc max =64A(GT+GTx)
L/L=2mV/A



CPU CORE

+VIN [25,36,39,41,42,44,46,47,49]
 +5VPCU [37,45,48]
 +VCCSA [6,41]
 +VCC_CORE [5]



+VCC_CORE

U-line 22(15W)

TDC:21A

Icc max:29A

L/L=2.4mV/A

U-line 23e(28W)

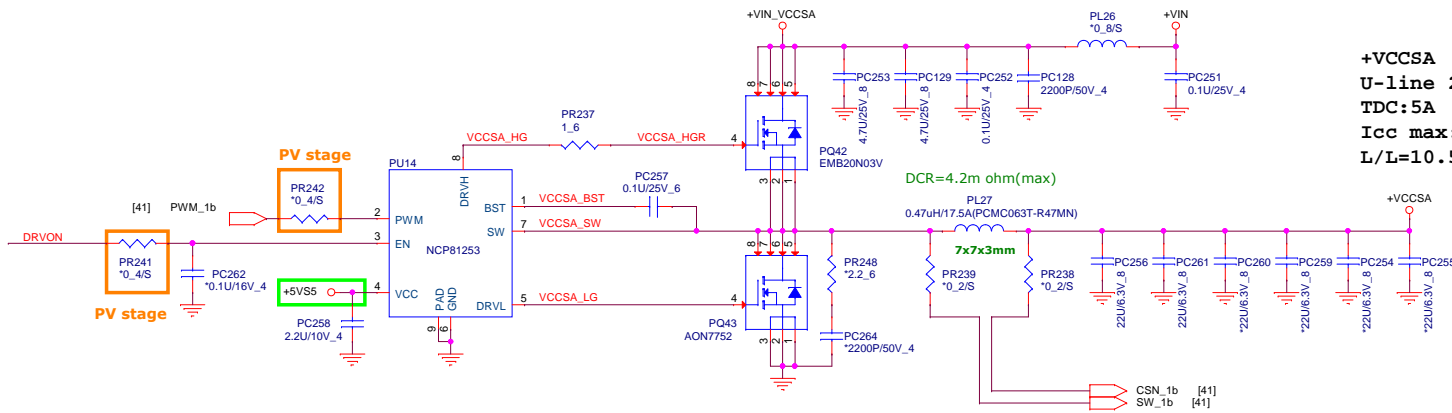
TDC:23A

Icc max:32A

L/L=2.4mV/A

43

VCCSA




+VCCSA

U-line 22&23e

TDC:5A

Icc max:5A

L/L=10.5mV/A

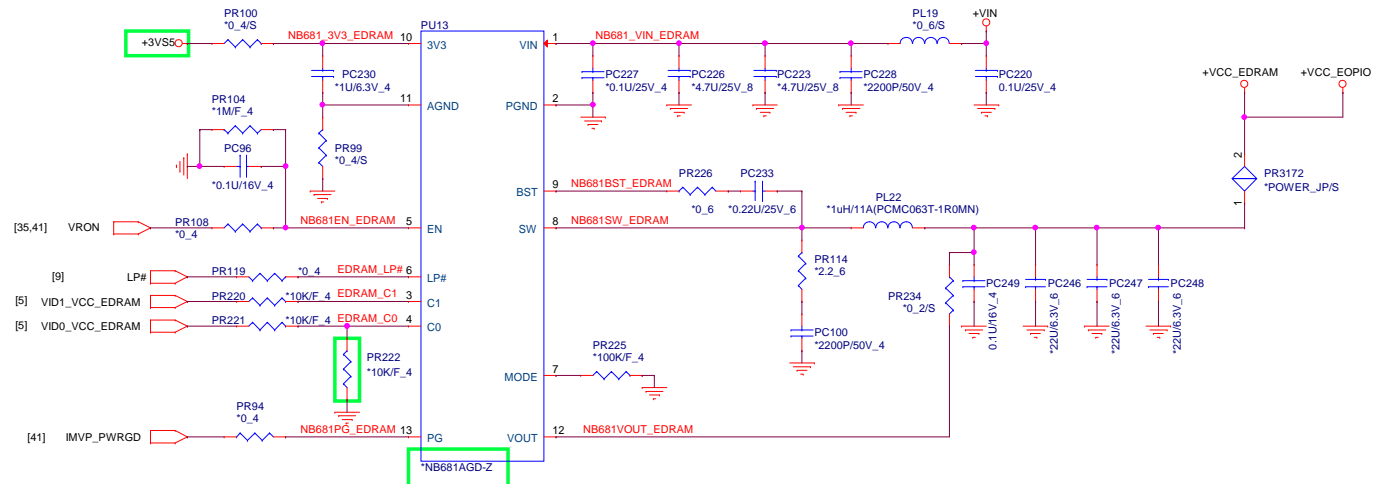
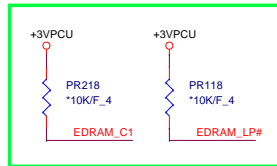


PROJECT : X1Q
Quanta Computer Inc.

Size	Document Number	Rev
Custom	+VCCSA/VCCSA (NCP81253)	
Date: Wednesday, July 20, 2016	Sheet 43 of 49	

+VIN [25,36,39,41,43,46,47,49]
 +3VPCU [6,13,29,31,34,37]
 +VCC_EOPIO [5]
 +VCC_EDRAM [5]
 +3VS5 [4,10,15,16,27,31,32,35,37,40,45,48]

+VCC_EDRAM +/- 5%
 Countinue current:4.5A
 Peak current:6A

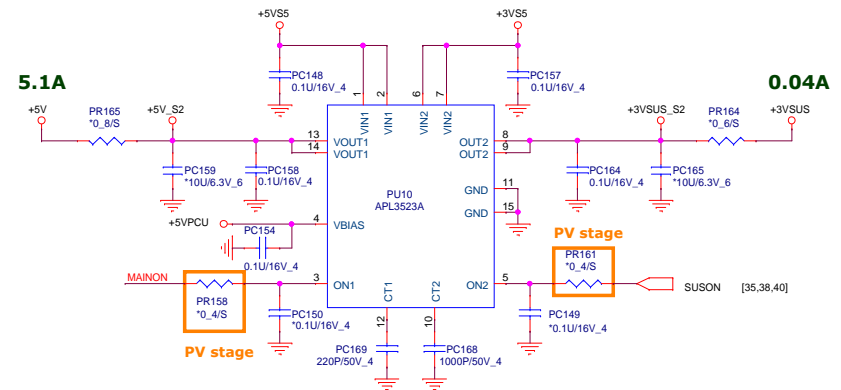


VCC_EDRAM

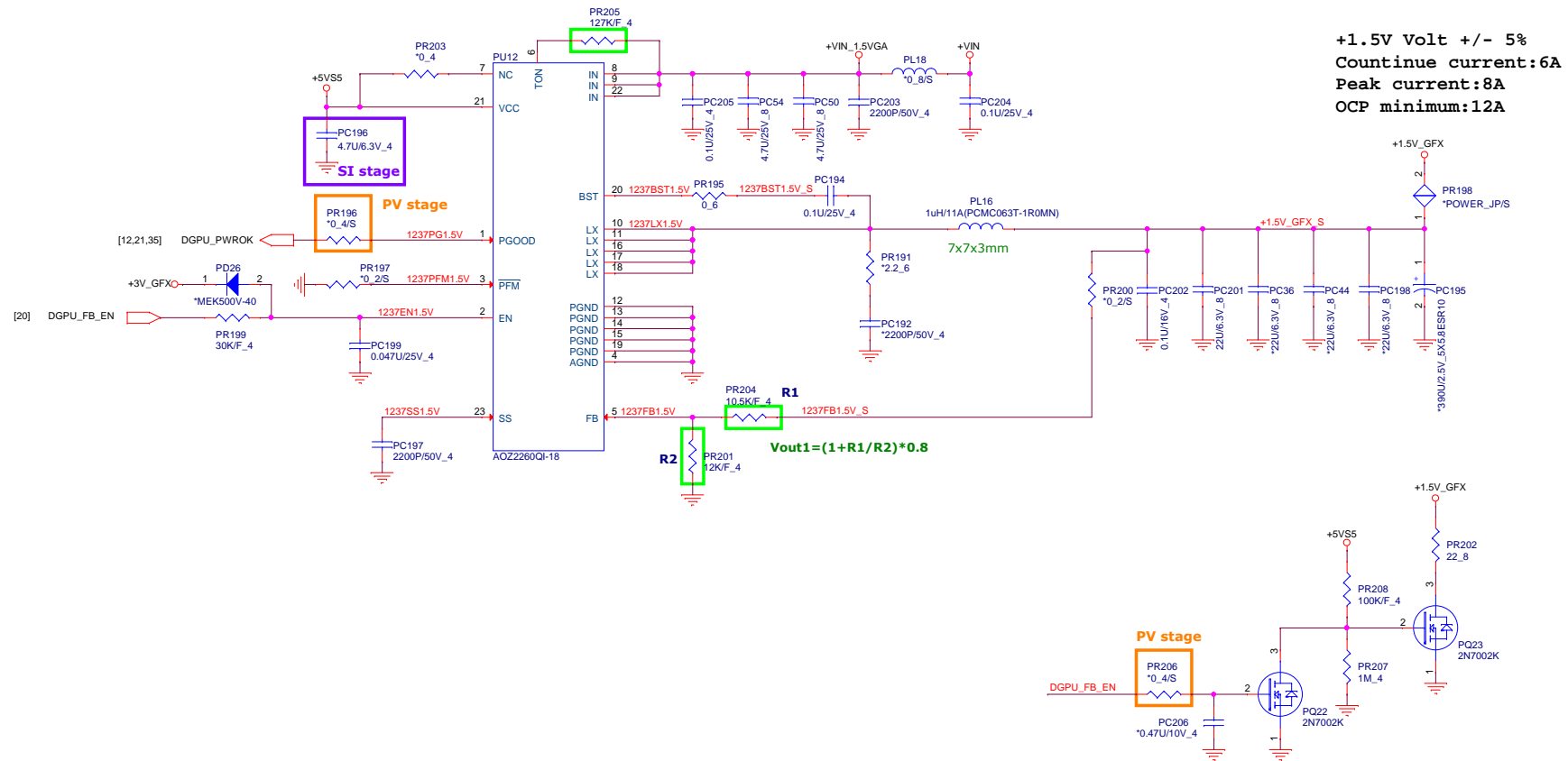
LP#	C1	C0	Vout
0	X	X	0
1	0	0	0.8
1	0	1	0.95
1	1	0	1.0
1	1	1	1.05

MODE

	VR rail	Resistor
M1	VCCIO	0
M2	PRIMCORE	Float
M3	EDRAM/EOPIO	100K
M4	other	150K



+VIN [25,36..39,41..44,46,49]
 +5VS5 [4,26,32,37..43,45,46,48]
 +1.5V_GFX[20,23,24]



+VIN	[25,36,39,41,44,46,47,49]
+3VS5	[4,10,15,16,27,31,32,35,37,40,44,45]
+5VS5	[4,26,32,37,43,45,47]
+3V_GFX	[19,21,22,46,47]
+3V_AON	[19,22,34]
+1.2VSUS	[3,6,17,18,38,40]
+1.05V_GFX	[19,21]

